

Preparation of the AC-LGAD test

Hanwen Wang
on behalf of the LGAD team

CEPC Silicon Tracker Group Meeting
2025.08.15

个人简介

- 王翰文，于北京航空航天大学（2016–2023年）和布鲁塞尔自由大学（2018–2023年）获得粒子物理学双博士学位。
- **博士期间**，我的研究主要集中在利用大型强子对撞机（LHC）上的紧凑型 μ 子线圈（CMS）探测器**测量希格斯玻色子性质**，作为 $H \rightarrow ZZ \rightarrow 2l2\nu$ off-shell分析的主要贡献者，首次发现了希格斯粒子离壳产生的证据，并实现了迄今为止最精确的希格斯玻色子宽度测量 [Nature Physics vol. 18, p1329–1334 \(2022\)](#)。
- 自2023年2月起，我在中国科学院高能物理研究所（IHEP）从事**博士后工作**，研究方向起始于中微子物理领域的光探测器技术
- nEXO无中微子双 β 衰变实验：极低本底硅晶圆转接板的研发 [Neutrino 2024 id. 294](#)
- JUNO-TAO反应堆中微子实验：大规模（4000+ 片）**硅光电倍增管**（SiPM）的低温(-50°C)性能测试与表征、老化测试、质量验收、探测器能量分辨率估计及探测器集成与安装工作。 [JINST 19 P07028](#), [Neutrino 2024 id. 279](#)
- 从2025年6月起，参与CEPC硅径迹探测器项目，参加研制原理样机的研制工作，承担OTK LGAD全面测试的计划与筹备、以及基于双相 CO_2 的半导体探测器冷却技术的研发，未来也将参与生产线上AC-LGAD全工艺流程的验证与优化。



Low Gain Avalanche Detectors (LGAD)

For collider physics (GeV particle detection, not single photon)

- Keep charge information
- High timing resolution (20-30 ps)

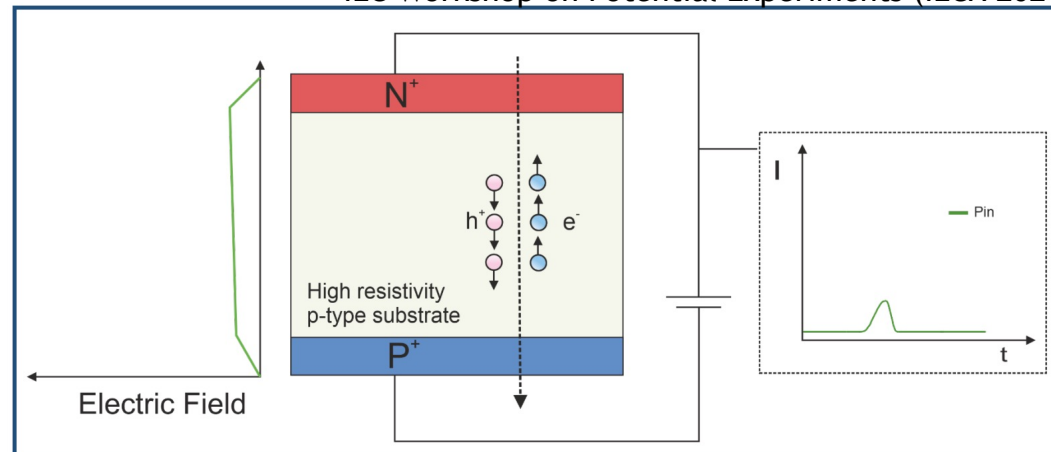
Low gain 'APD'



LGAD

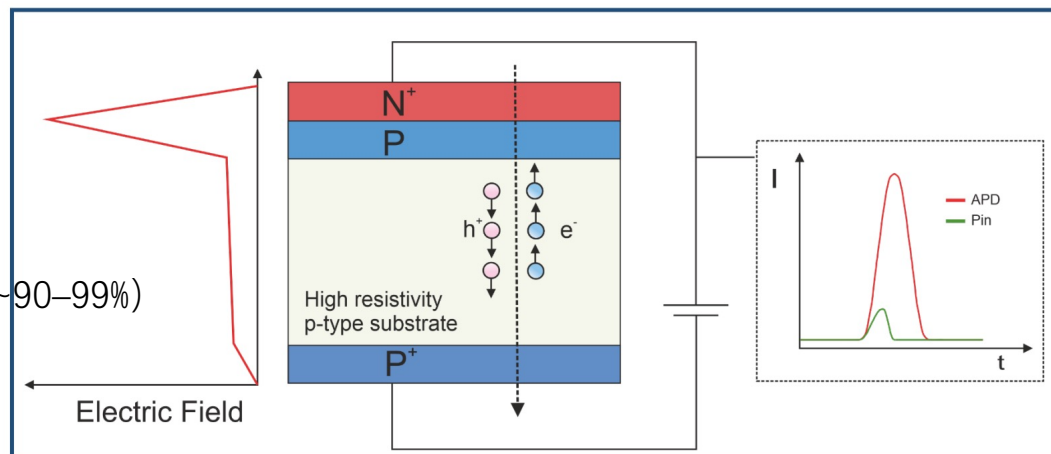
PIN
 $n^+ - p$

漂移时间分布宽,
时间分辨较差
(通常 > 100 ps)



APD
 $n^+ - \pi - p$

反偏接近雪崩击穿电压 (~90-99%)
全漂移区形成高电场
时间分辨可以做到几百ps
但受限于增益 ($1e2 \sim 1e3$)
和SNR

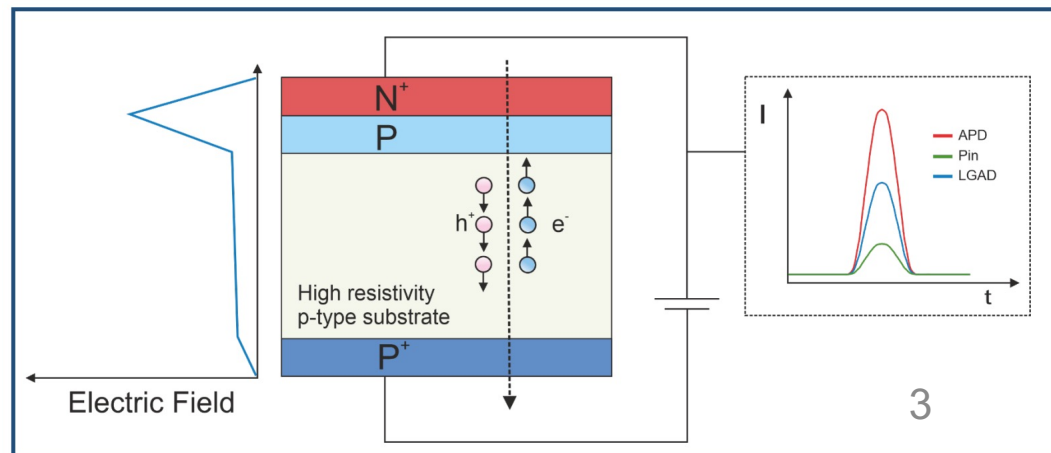


SAPD/SiPM

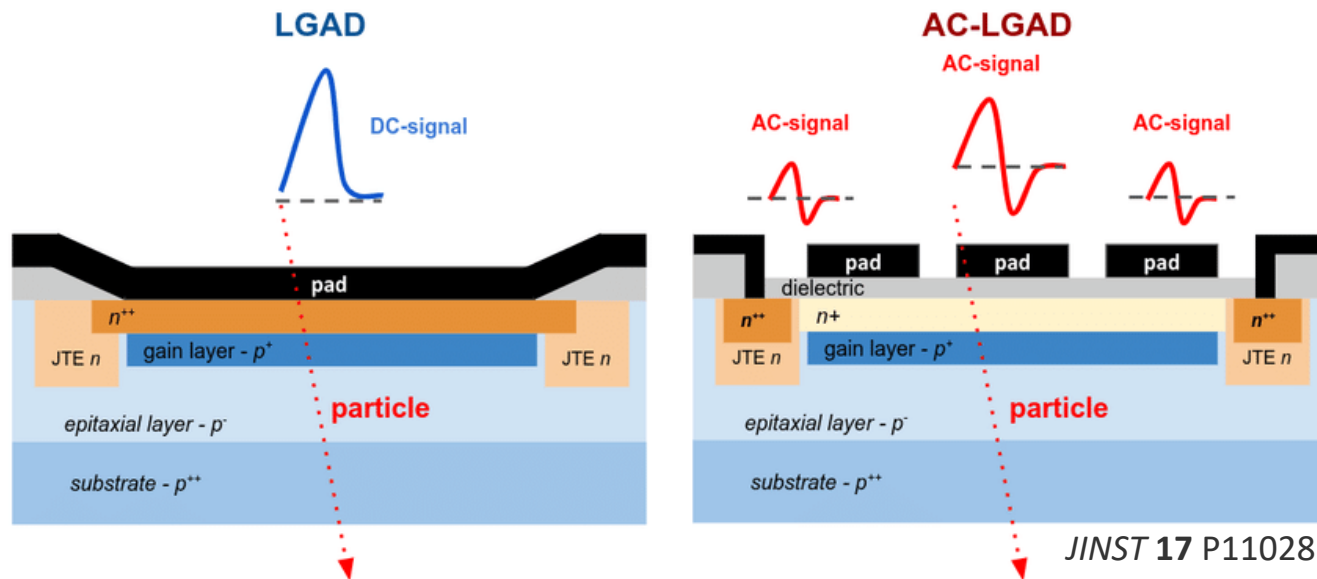
工作在击穿电压之上 (盖革模式)
需要引入淬灭等方式停止雪崩
增益更大 $1e6 \sim 1e7$

LGAD
 $n^{++} - p^+ - p$

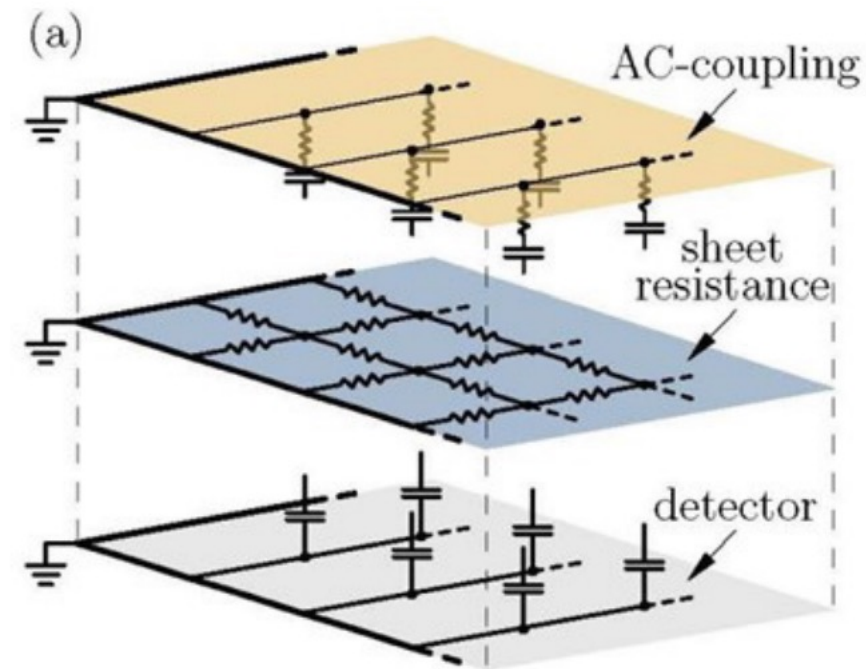
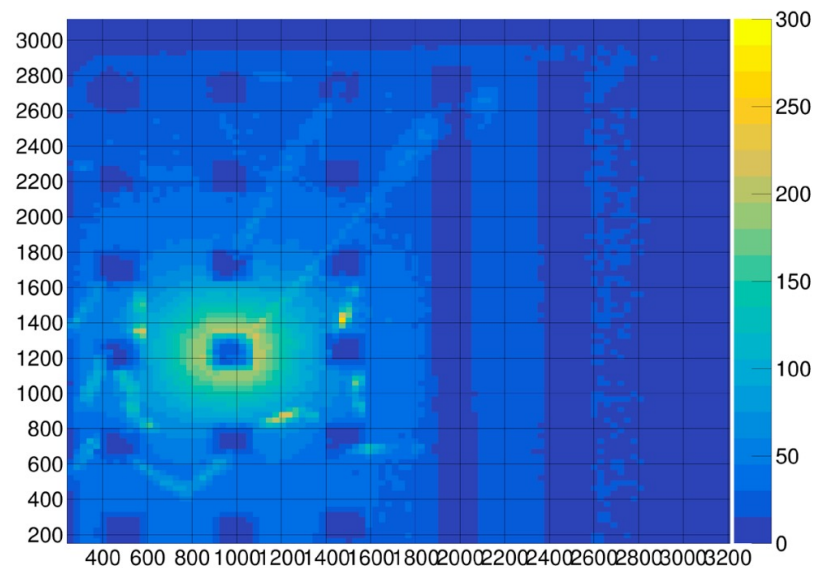
“低增益 APD”
工作低于击穿电压
(一般为 200-400 V)
高 SNR
高时间分辨 (ps 级)



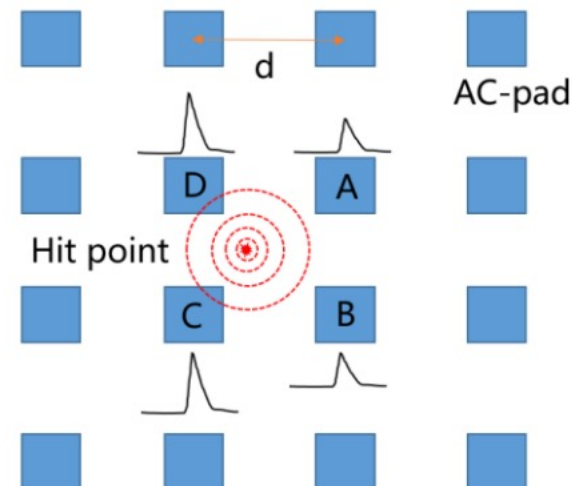
AC-LGAD



Sheet resistance of N+layer: signal spread a few 100 μm in a laser scan.



Signal of AC-LGAD



Development of LGAD for ATLAS HGTD and CEPC TOF out-tracker
赵梅, 第十四届全国粒子物理学术会议(2024)

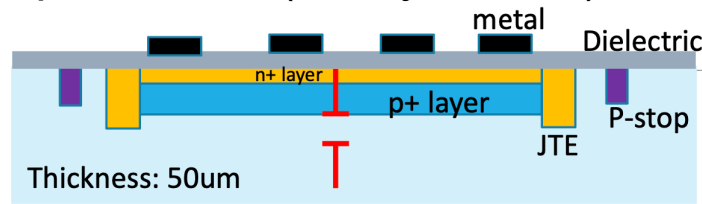
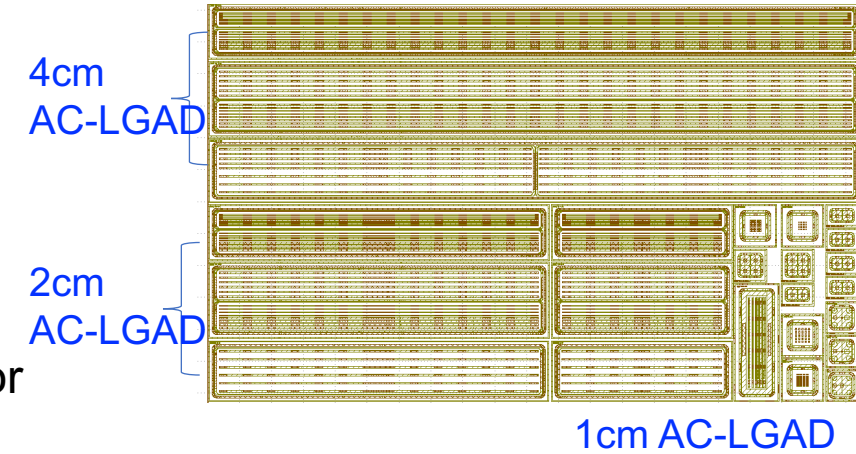


Latest Progress on AC-LGAD Sensor R&D

From Mei Zhao

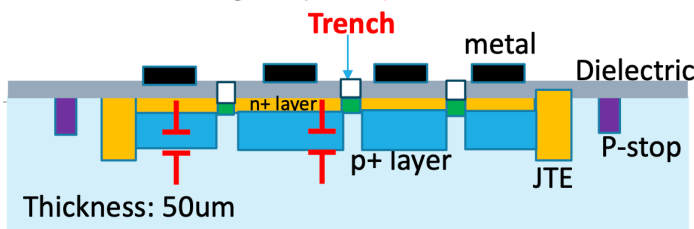
■ New IHEP AC-LGAD strip sensor prototype: submitted for tap-out in March 2025. The new layout and design include:

- Strip lengths: 1 cm, 2 cm, and 4 cm
- Strip pitch sizes: 100 μm , 200 μm , and 500 μm
- Electrode widths: 25 μm , 50 μm , and 100 μm
- Optimized isolated structure design and EPI thickness to reduce sensor capacitance (correlated with power consumption)
- Process design optimization (n+ layer dose) for better spatial resolution

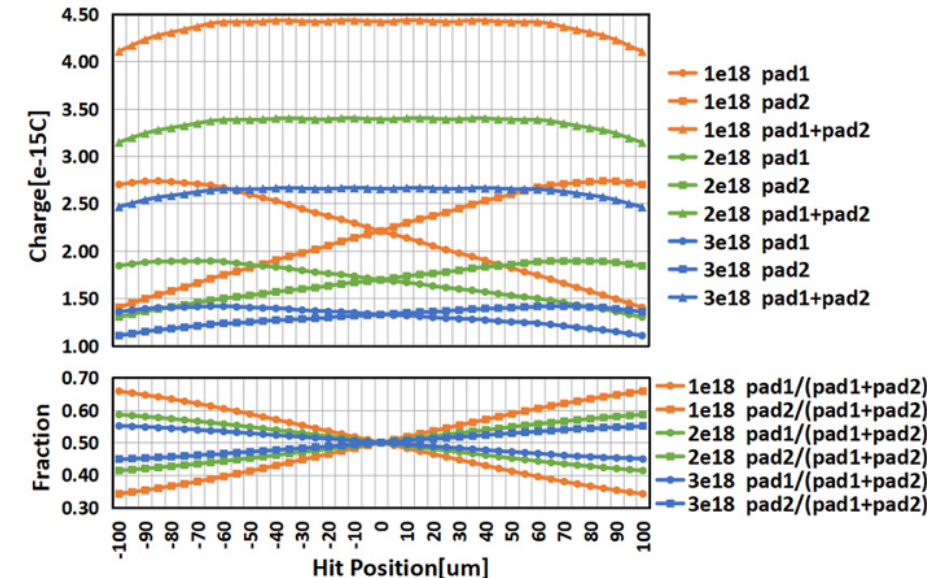
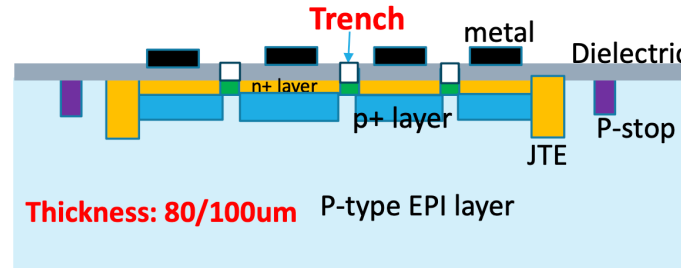


Introducing isolated structure:

$$C = \epsilon_0 * \epsilon_r * A / d$$



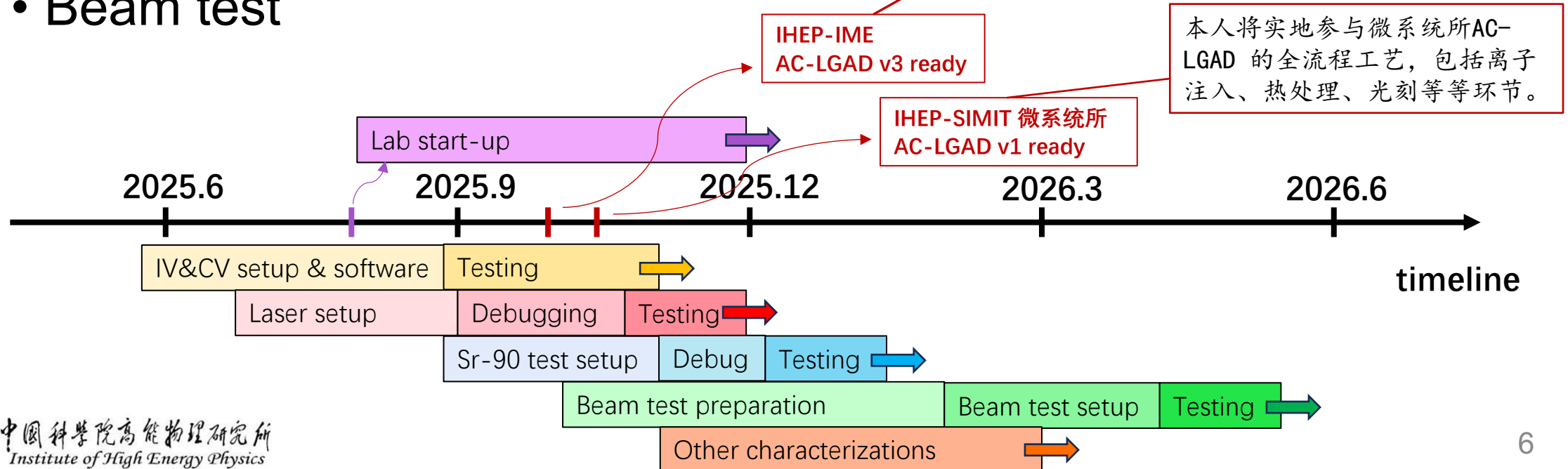
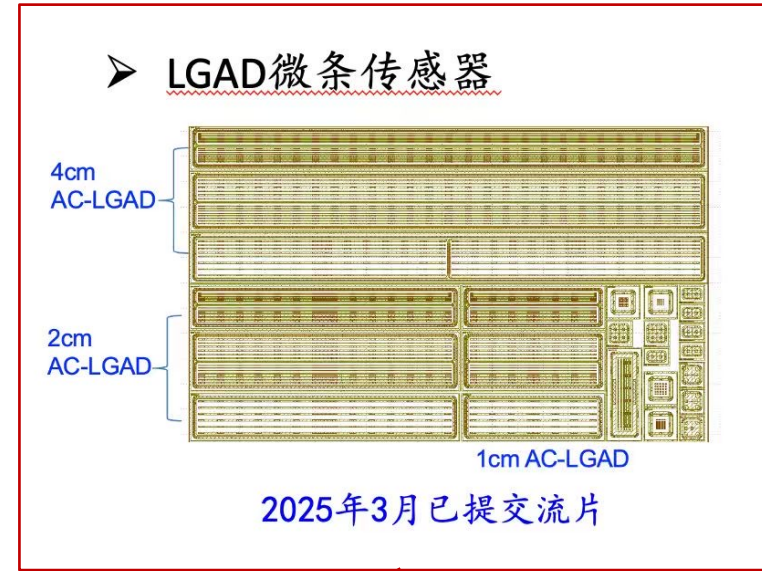
Increasing EPI thickness: $C = \epsilon_0 * \epsilon_r * A / d$ ↑



The sensor test will be launched once we received the latest tap-out.

LGAD tests

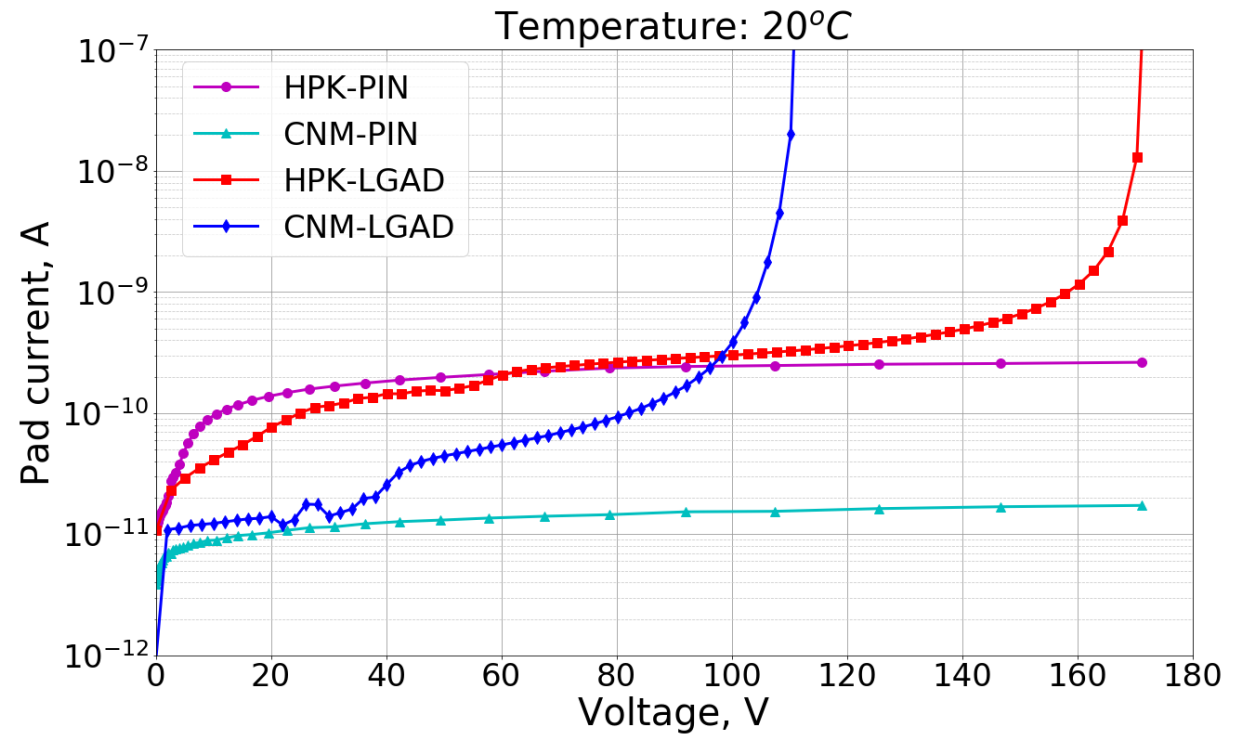
- I-V test & C-V test
- NIR TCT for spatial resolution
- ^{90}Sr test for time resolution
- Beam test



I-V & C-V tests

I-V test

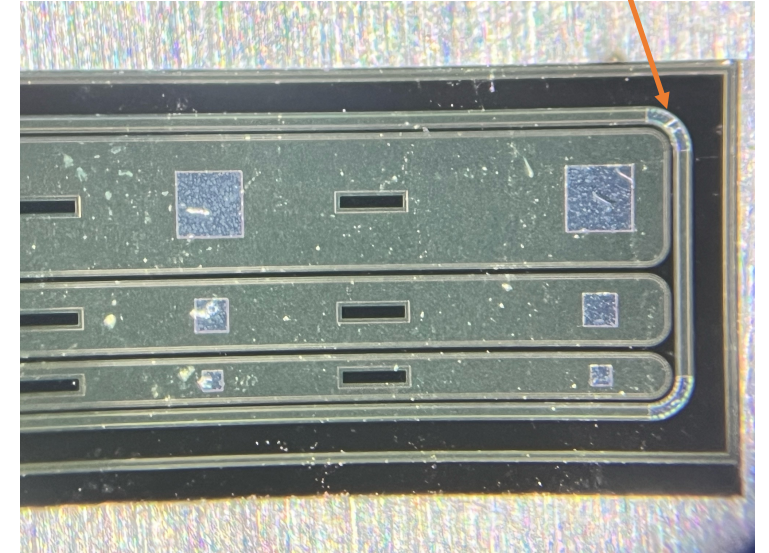
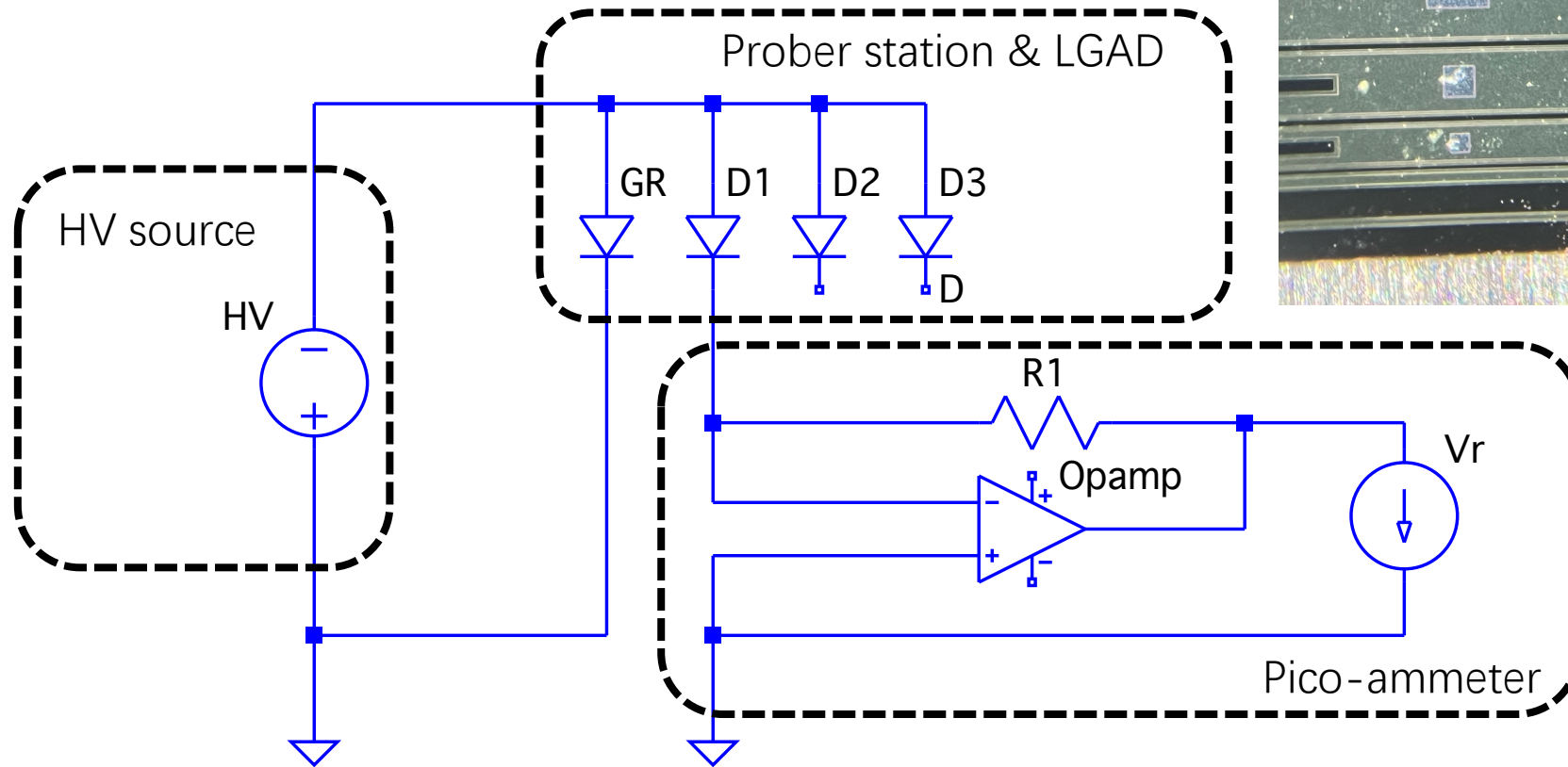
- Standard method to evaluate semiconductor electrical performance
- Result: I-V curve (voltage vs. current)
- Reveals key parameters: **breakdown voltage, leakage current, on-resistance**



<https://cds.cern.ch/record/2776521/plots>

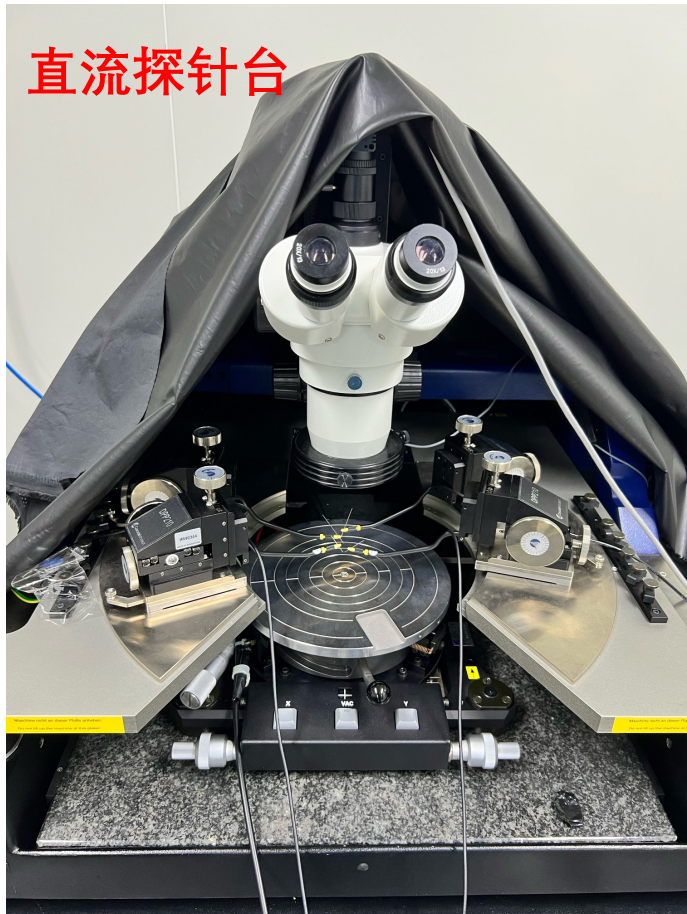
Guard Ring

I-V test schematic



I-V test equipment

直流探针台



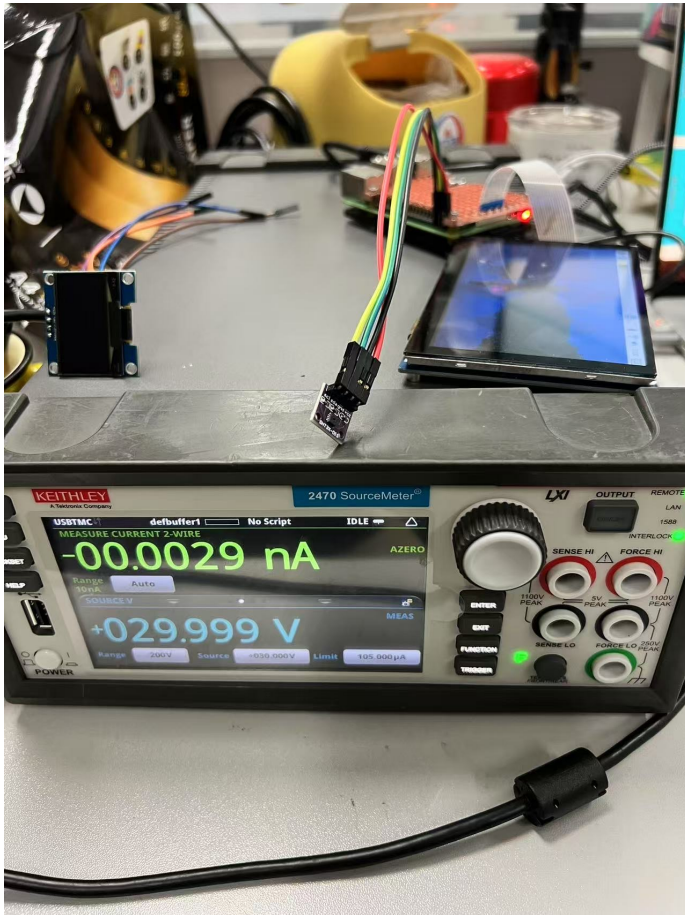
高压源（临时）
Keithley 2470 ($\pm 1000\text{V}$),
Keithley 6487 ($\pm 500\text{V}$)



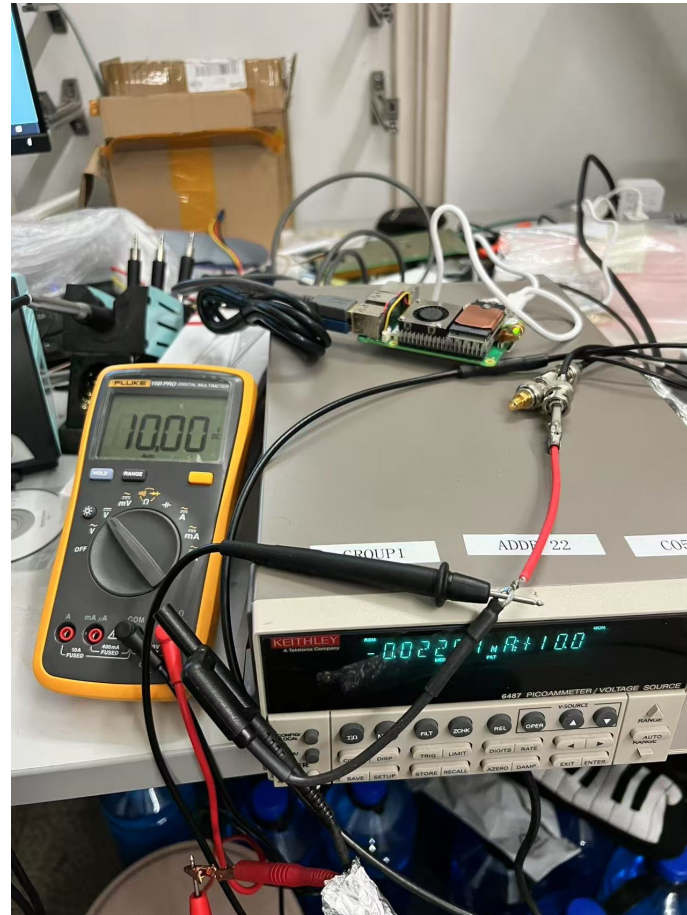
皮安表
keithley 6487,
keithley 6485



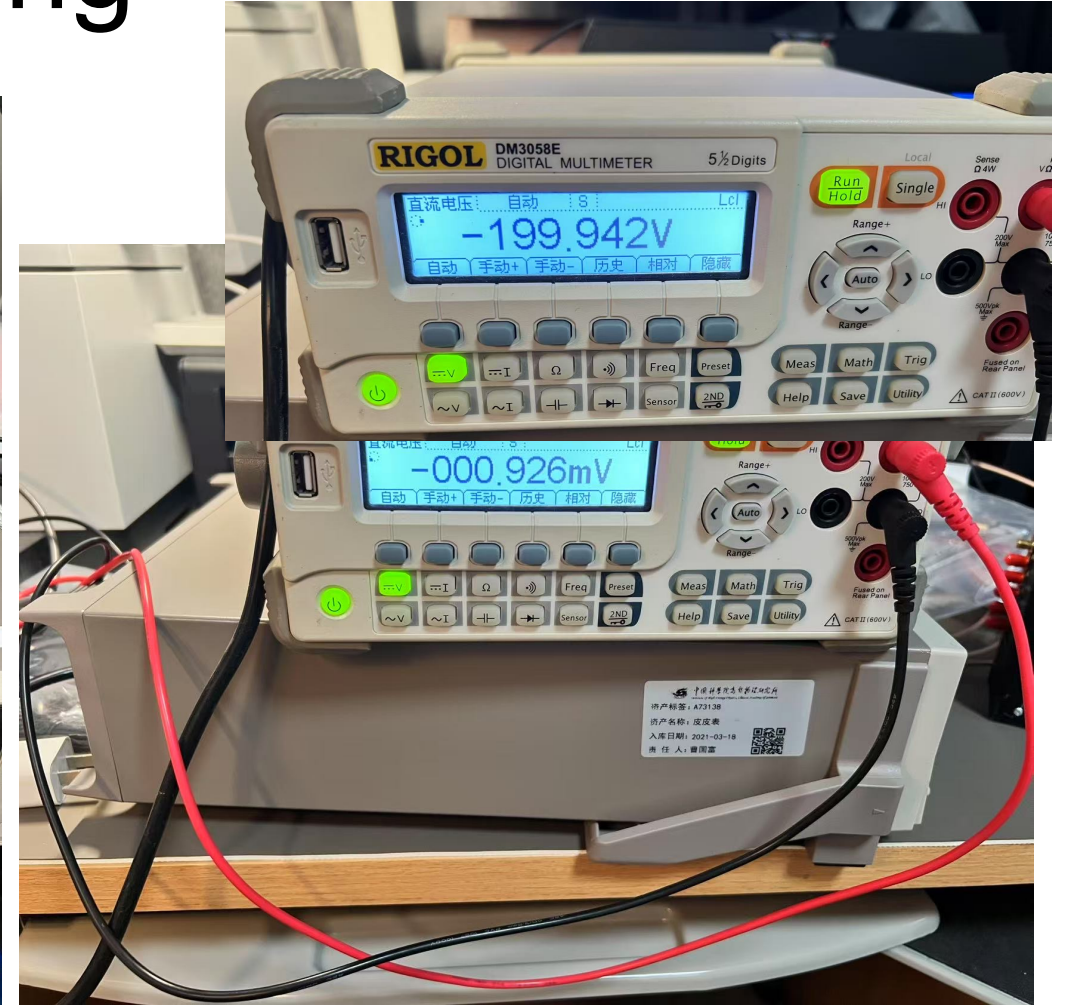
Script control & debugging



Keithley 2470 HV output test



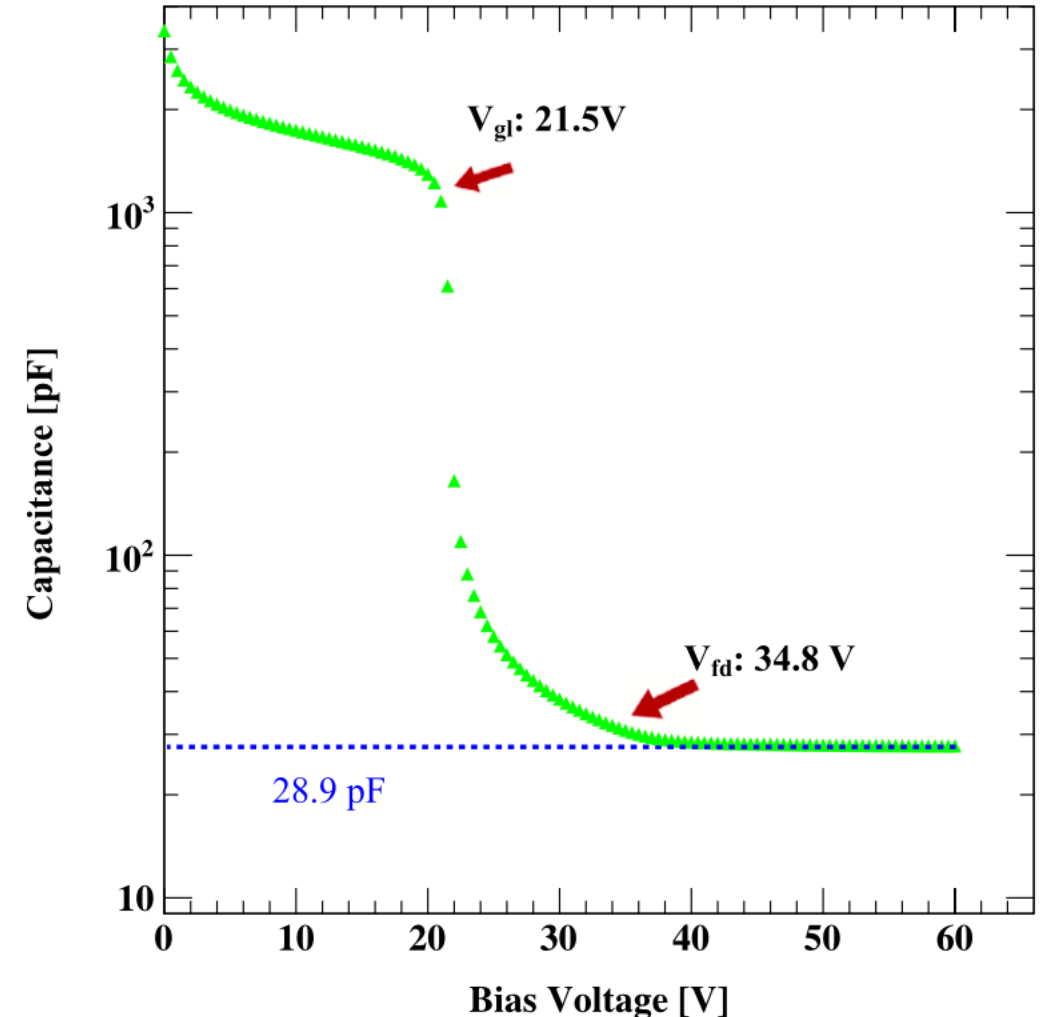
Keithley 6487 HV output test



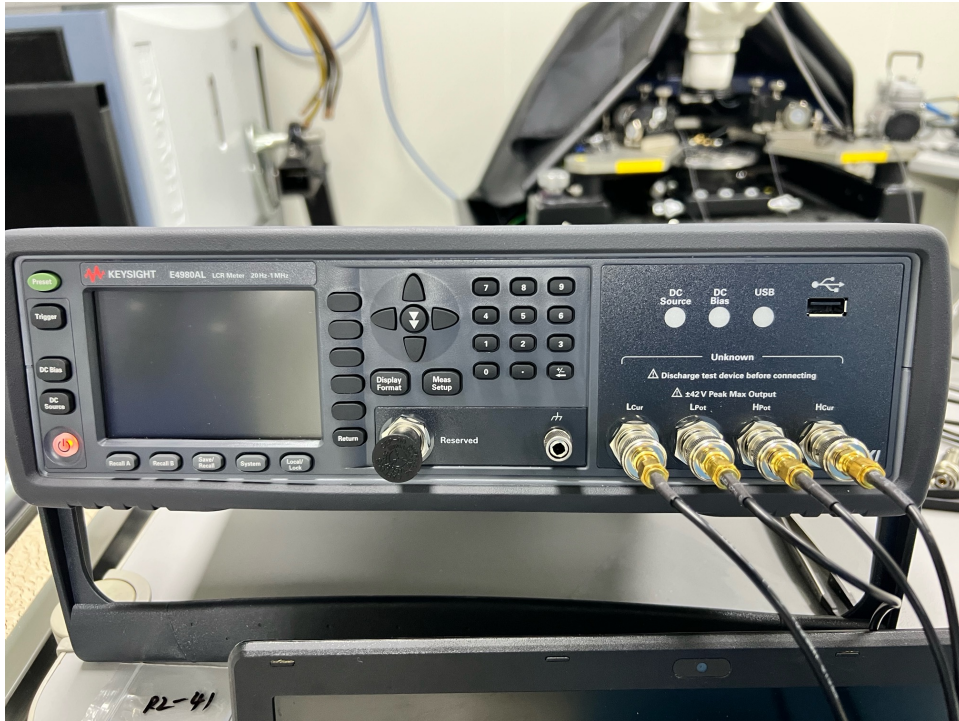
C-V test

[NIM A.2024.169203](#)

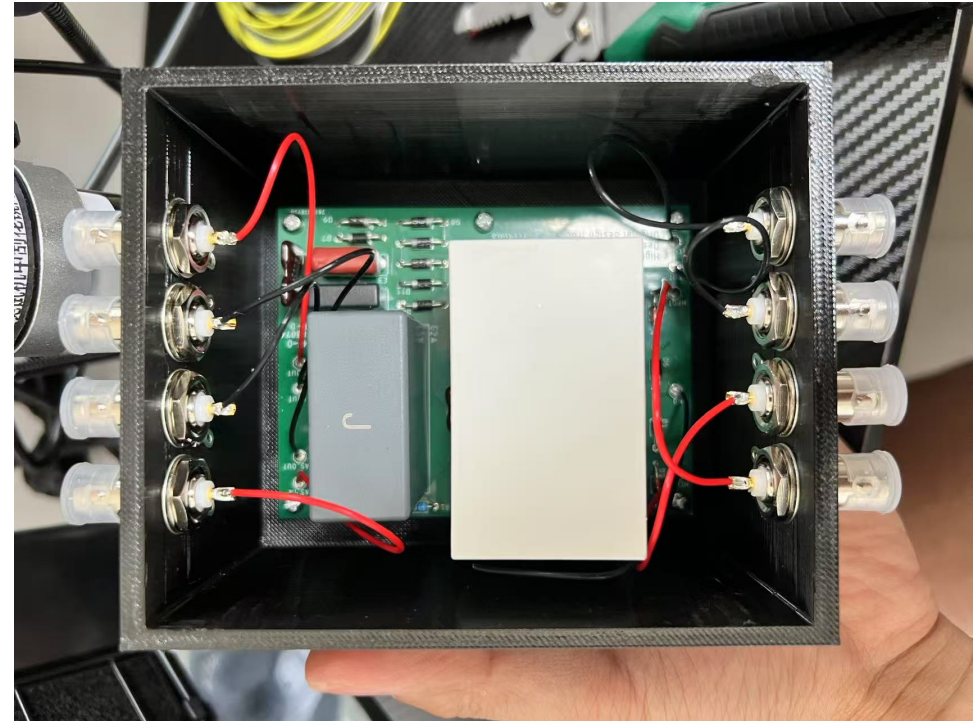
- Also a standard semiconductor test
- **C-V curve** reveals key parameters:
 - $V_{gl} = 21.5 \text{ V}$ Gain Layer Depletion: onset of gain layer depletion; capacitance drops rapidly
 - $V_{fd} = 34.8 \text{ V}$ Full Depletion Voltage
 - Plateau capacitance $\approx 28.9 \text{ pF}$: minimum junction capacitance
 - Further extraction: **depletion depth**, etc.



C-V test equipment



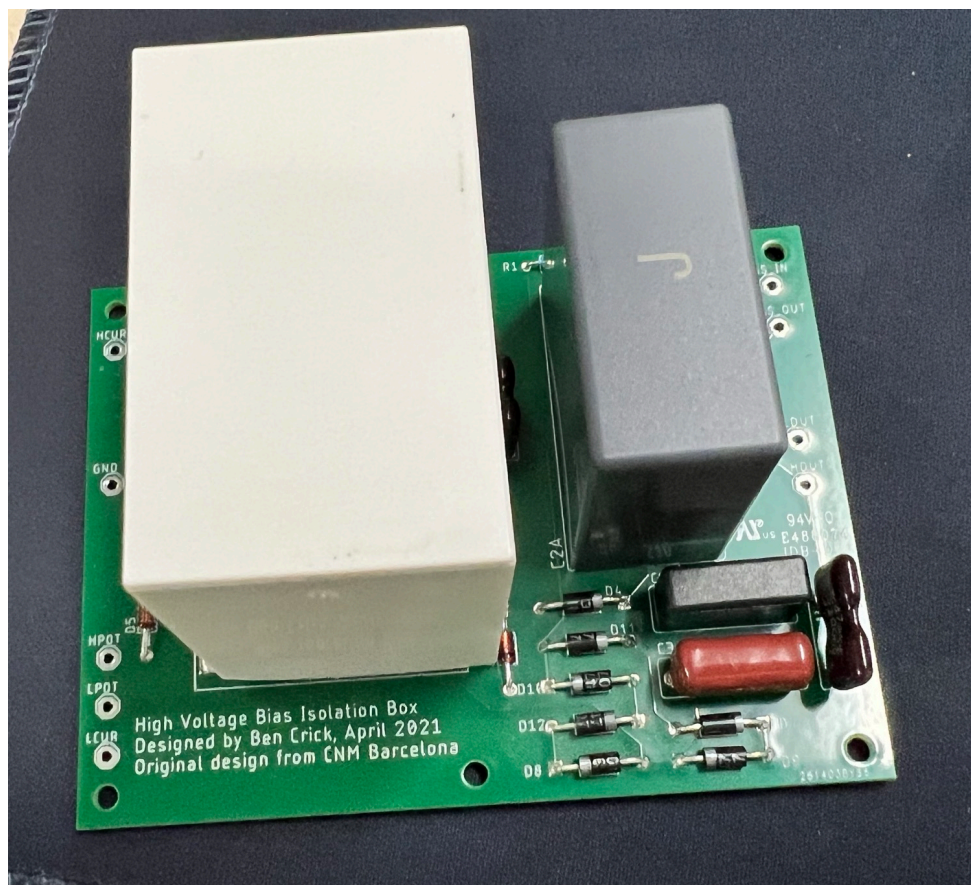
LCR meter



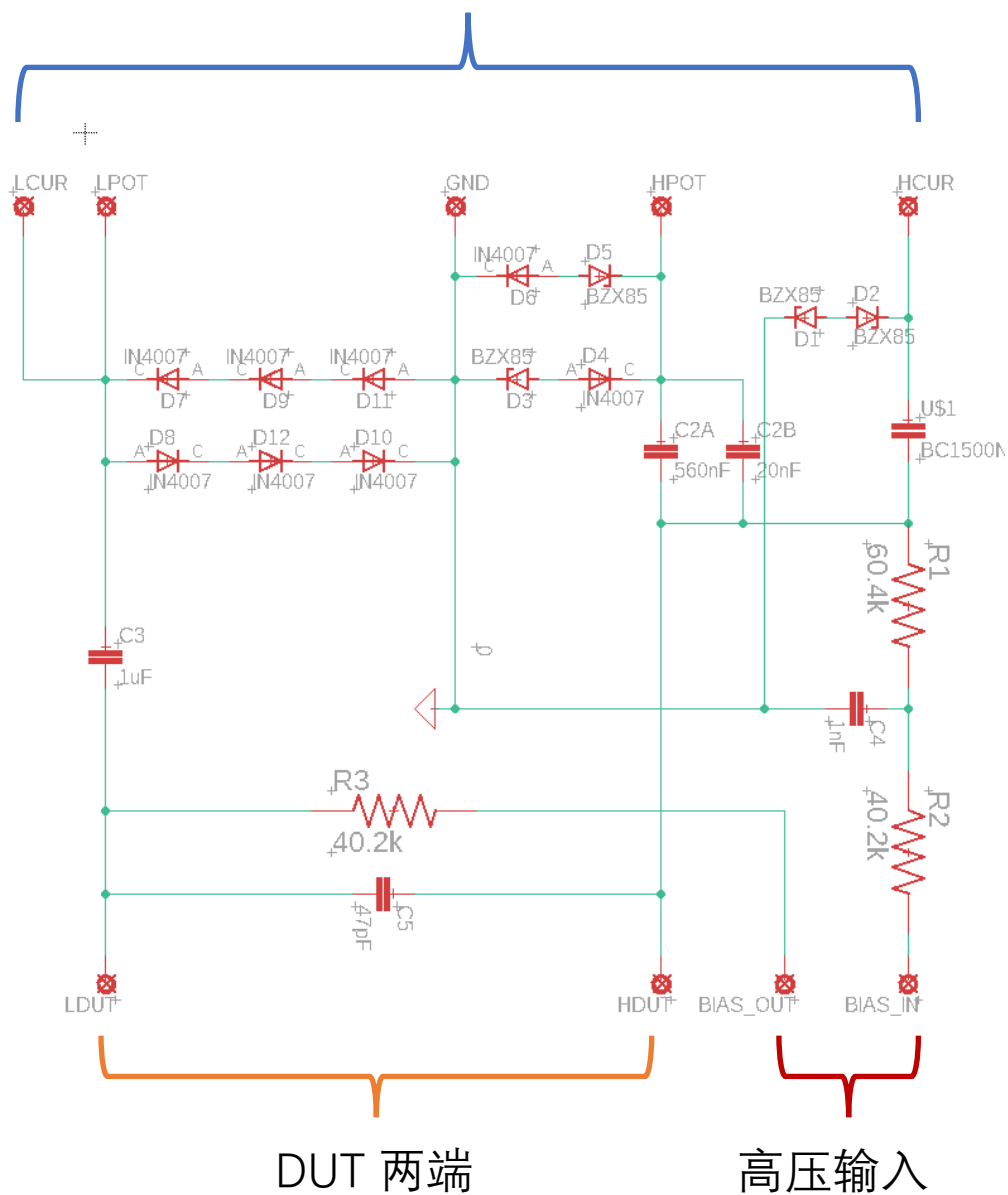
Bias-tee box

叠加直流偏压 (Bias) 与交流小信号 (AC)

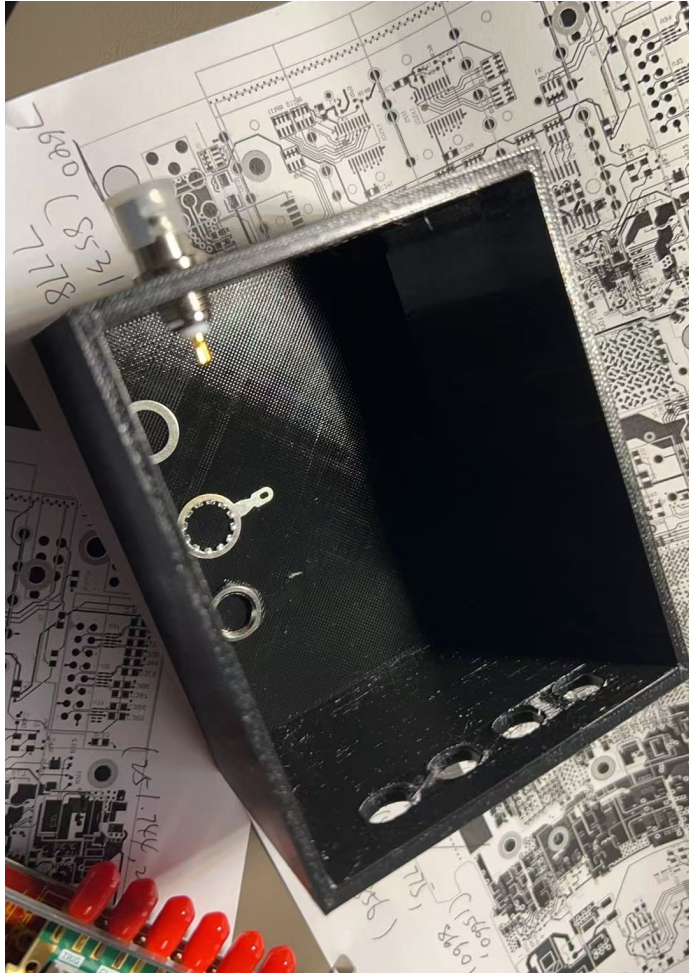
Bias-tee schematic



4 terminal 接LCR表



3D printed box & Soldering



LGAD I-V & C-V Measurement

Realtime Temp. & Humi.
monitored with SHT35 sensor

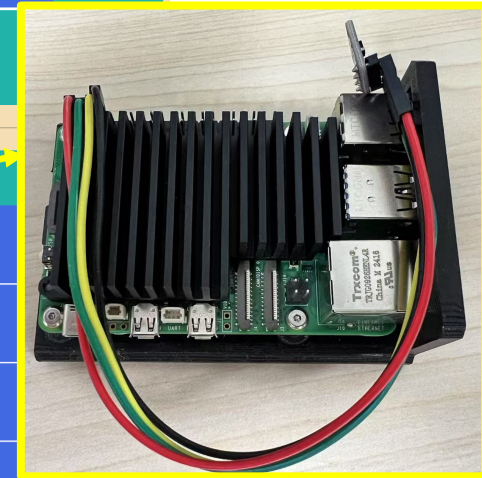
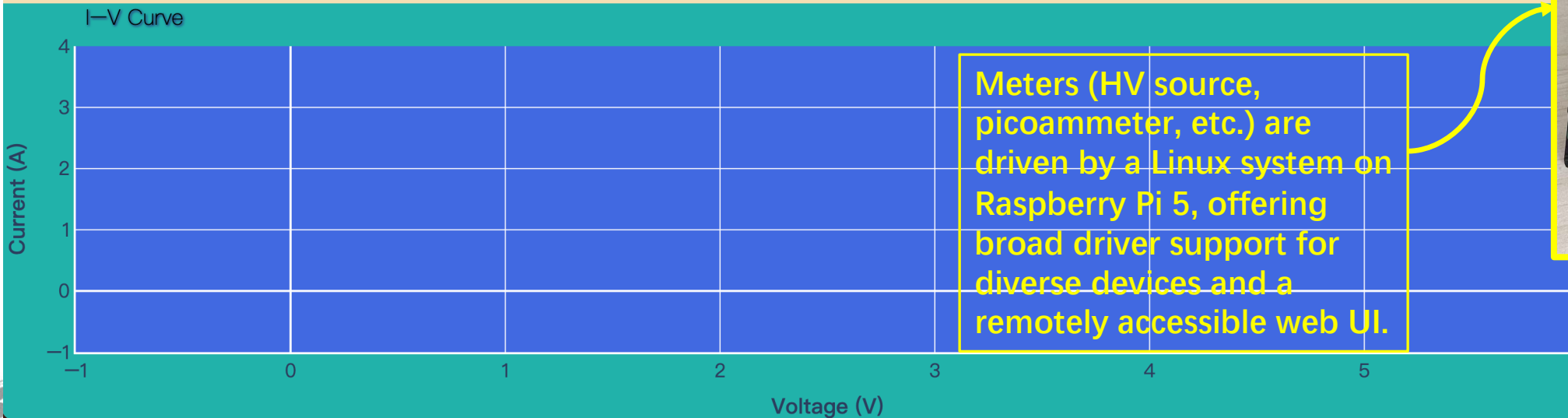
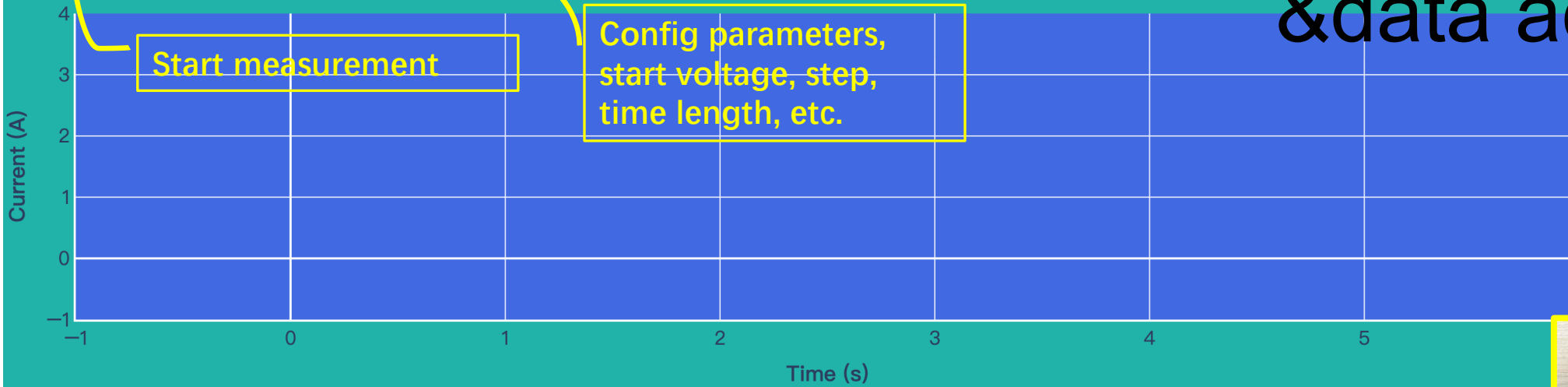
Dedicated UI
for monitoring
& data acquisition

Start Measurement Stop Measurement Config Parameters Plot IV Curve Plot CV Curve

Temperature: 26.0 °C | Humidity: 62.6 %

No data yet. Click 'Start Measurement' to begin.

Waiting for measurement to start...



LGAD I-V & C-V Measurement

Start Measurement Stop Measurement **Config Parameters** Plot IV Curve Plot CV Curve

Measurement Configuration

Start Voltage:

Stop Voltage:

Step Voltage:

Measurement Duration (s):

Sample Interval (s):

Stabilization Time (s):

Maximum Current (μ A):

AC Voltage (mV):

AC Frequency (kHz):

For I-V

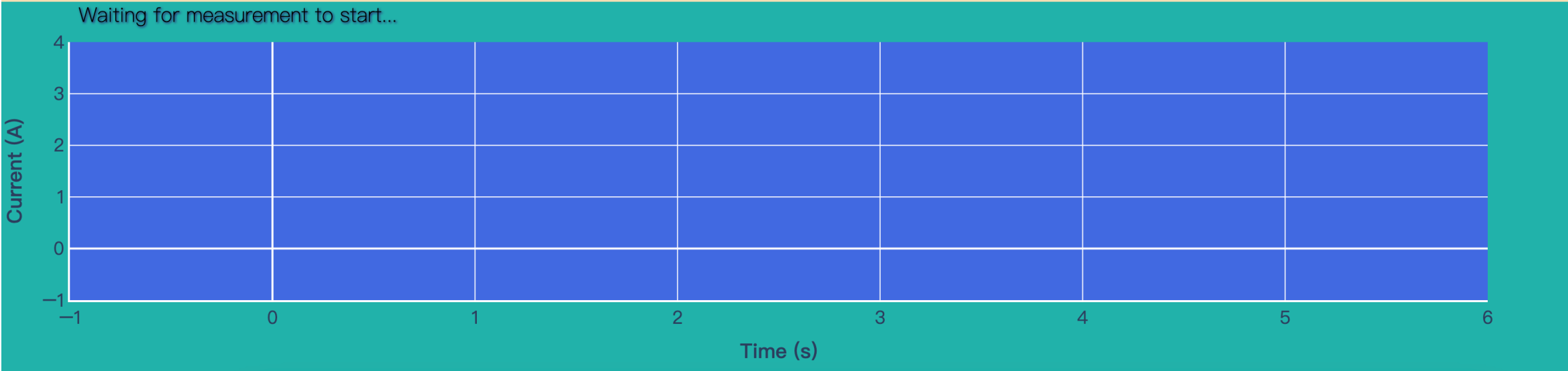
Config parameters,
start voltage, step,
time length, etc.

Preserved for C-V test

Confirm Cancel

Temperature: 26.4 °C | Humidity: 62.0 %

No data yet. Click 'Start Measurement' to begin.

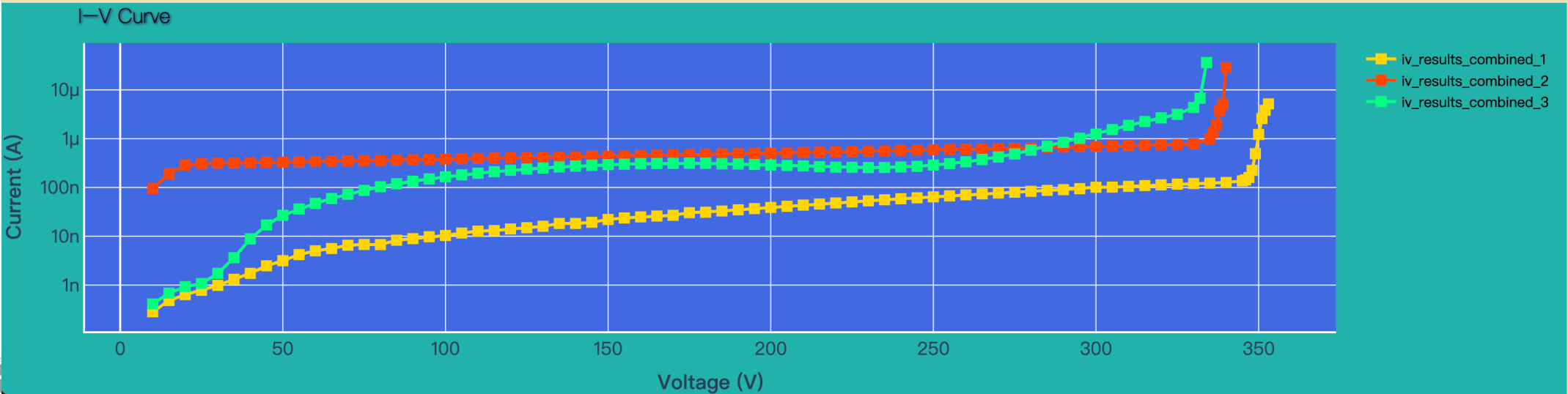
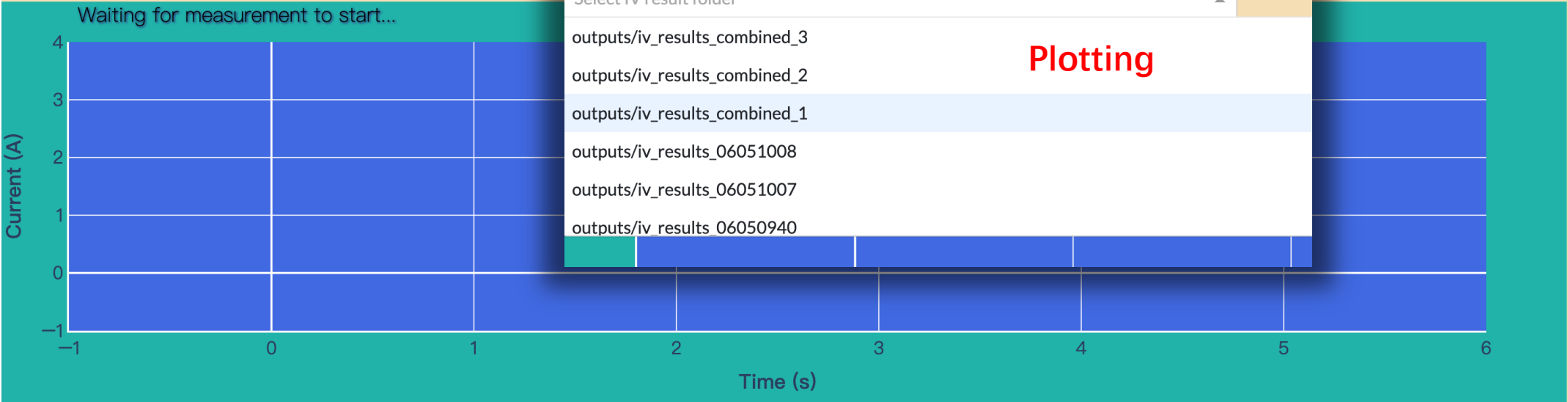


LGAD I-V & C-V Measurement

Start Measurement Stop Measurement Config Parameters **Plot IV Curve** Plot CV Curve

Temperature: 26.0 °C | Humidity: 62.7 %

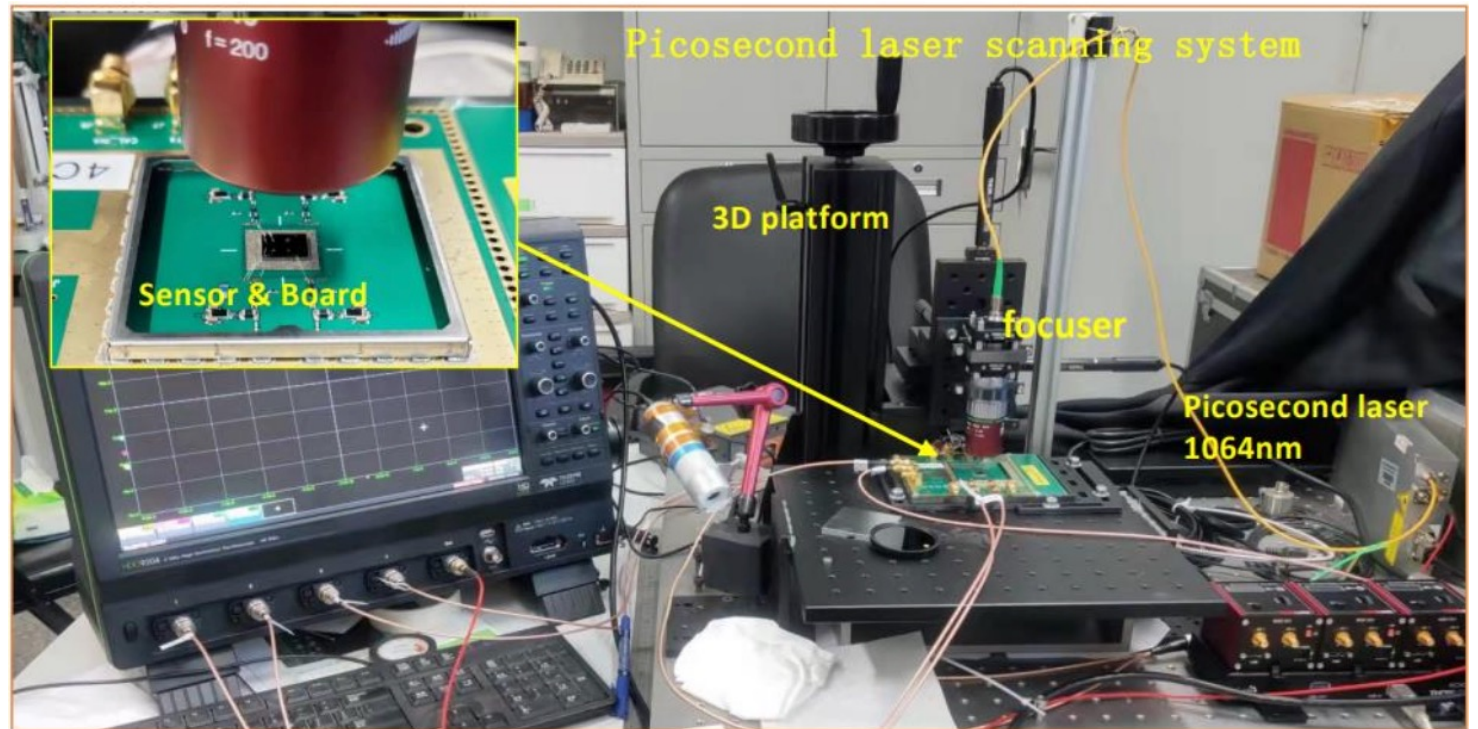
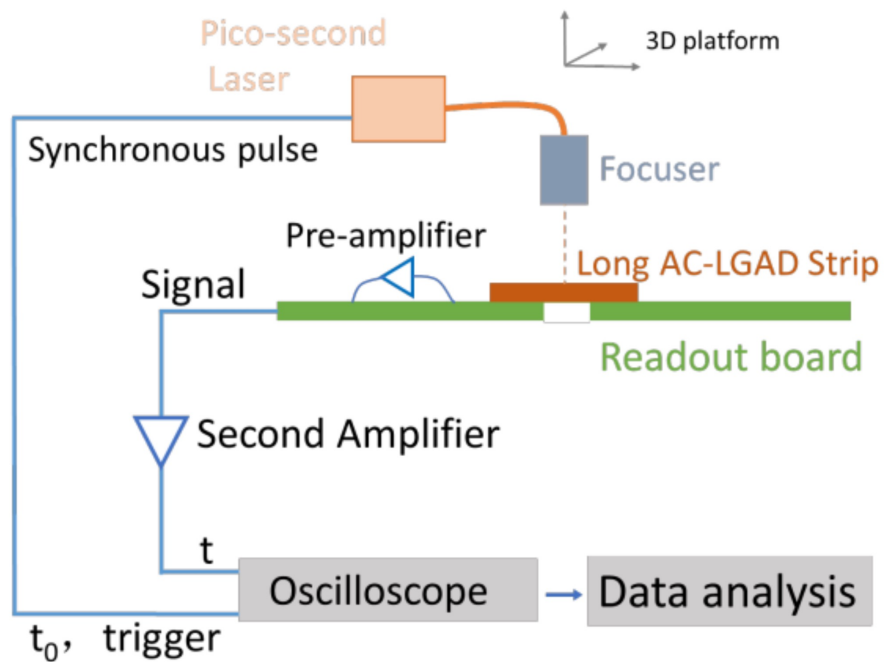
No data yet. Click 'Start Measurement' to begin.



Laser test

NIR TCT for spatial resolution study

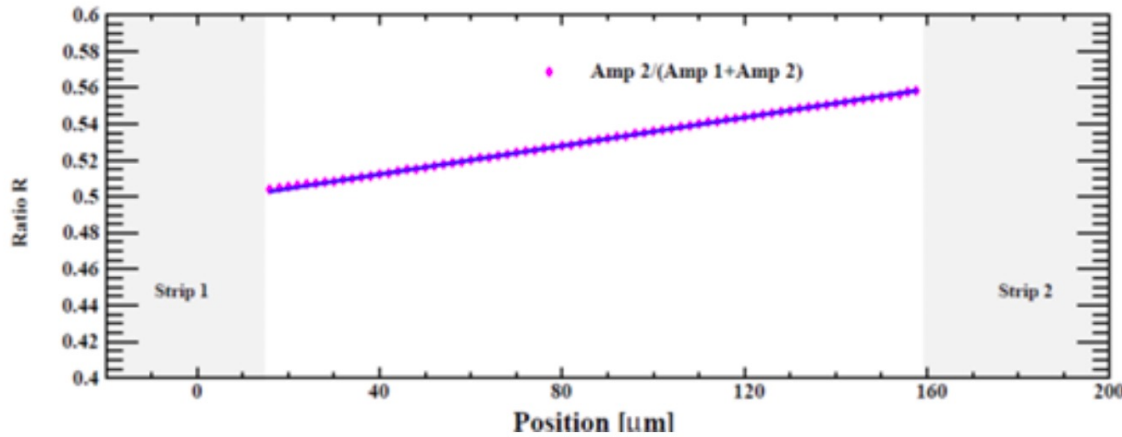
Laser test & spatial resolution



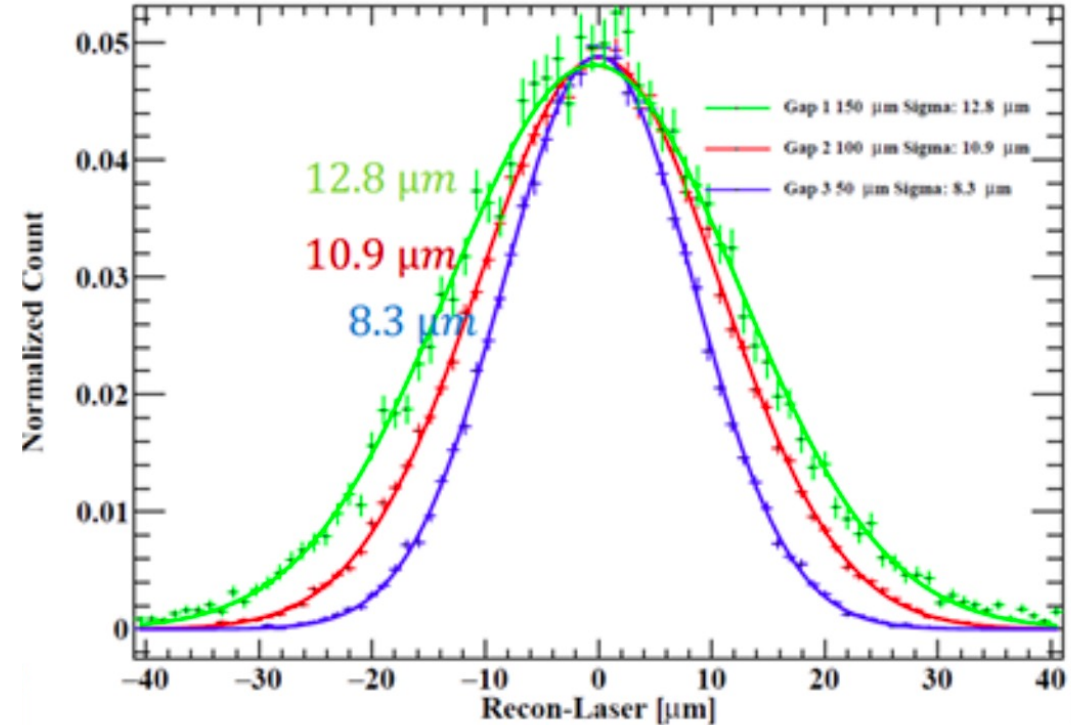
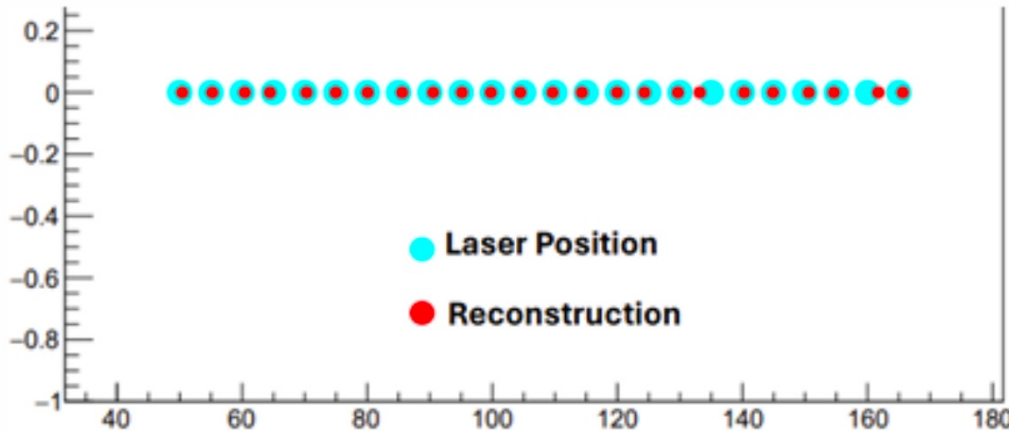
Picosecond laser (1064 nm) & x-y scanning system with step accuracy < 1 μ m

Laser test & spatial resolution

Amplitude information



Position reconstruction



Position reconstructed by amplitude ratio among different channels.
Spatial resolution of a certain laser point is derived with statistical methods (1D / 2D gaussian distribution).



NIR Picosecond Laser

Center wavelength: 1064 nm

Pulse width: < 8 ps

Pulse energy: 0.5 – 3 nJ

Average power: 6 – 200 mW

Peak power consumption: > 350 W

Spectral width: < 0.5 nm

Repetition rate: 20 MHz

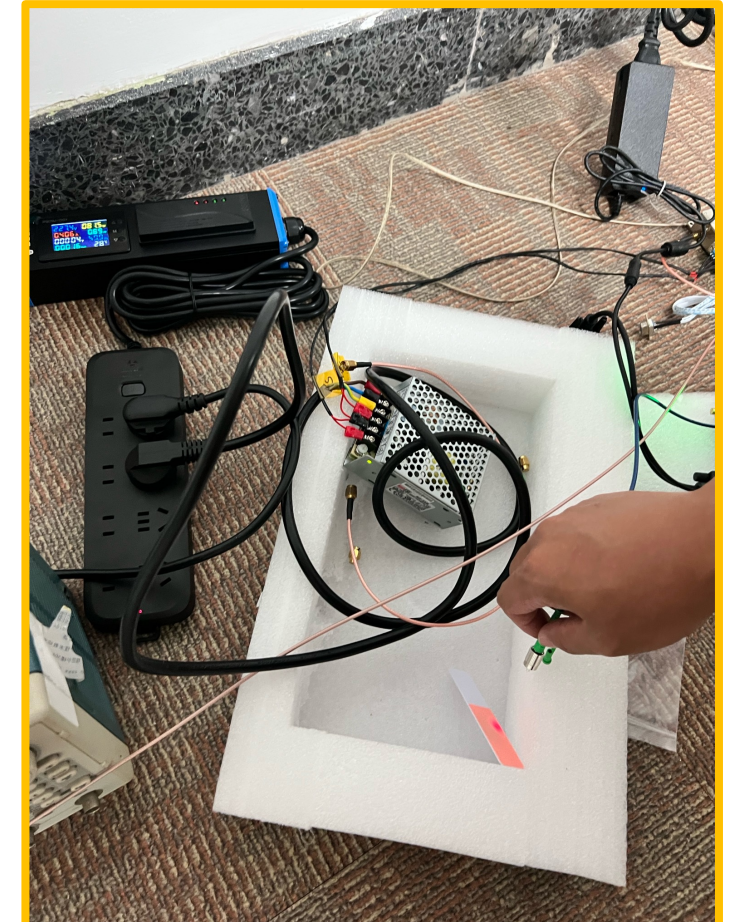
Polarization extinction ratio: > 100 : 1

Power stability: < 1 % RMS @ 3 h

Beam quality: TEM₀₀, M² < 1.1

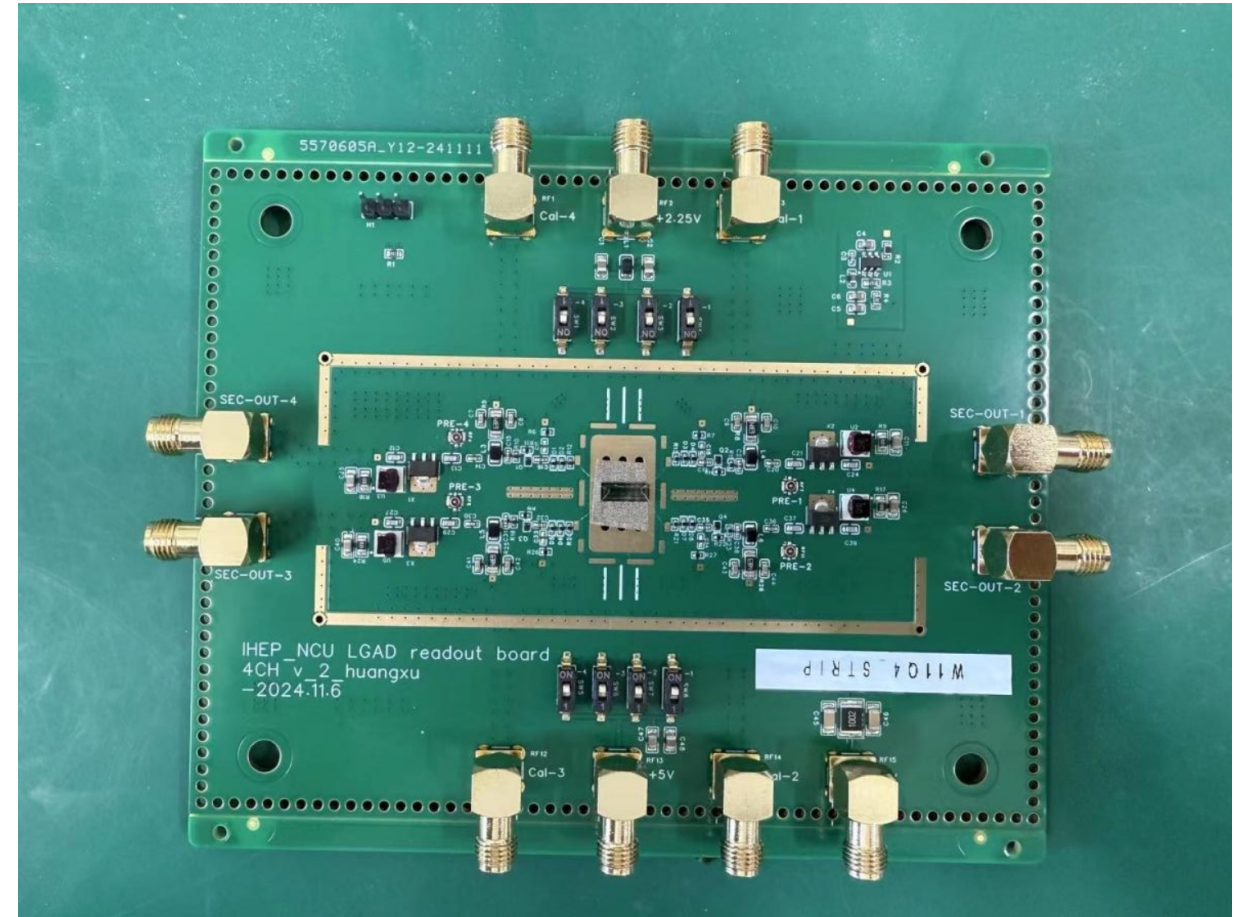
Output: Polarization-maintaining fiber

Cooling: Air cooling



4-ch Readout board

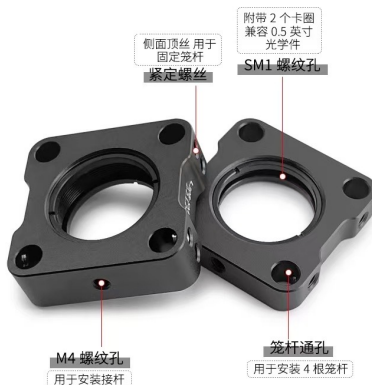
- 2-stage fast amplification (Gain~70)
- Chip mounted through electrically conductive glue (substrate) & **wire bonding** (top pad)
- Single channel gain can be calibrated



Optical Setup

卓立汉光双频阻尼隔振光学平台
DRN24-12 2400 × 1200 × 800

GBE15-B - 15X
消色差伽利略扩束器



同轴系统

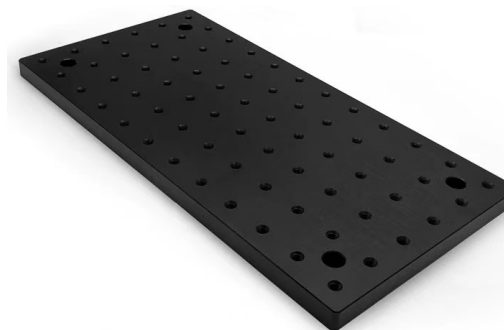


三丰M PLAN APO
NIR 20X 红外物镜



固定式非球面
光纤准直器

外螺纹 SM1(1.035"-40)
内螺纹 M6-M21 螺纹多种型号
专用于 1 英寸透镜等光学元件转小透镜转接件



步进电机位移滑台

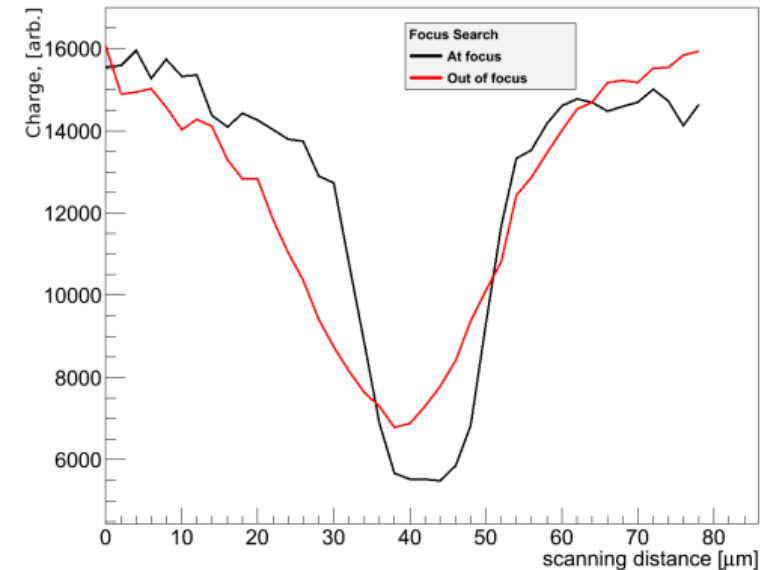
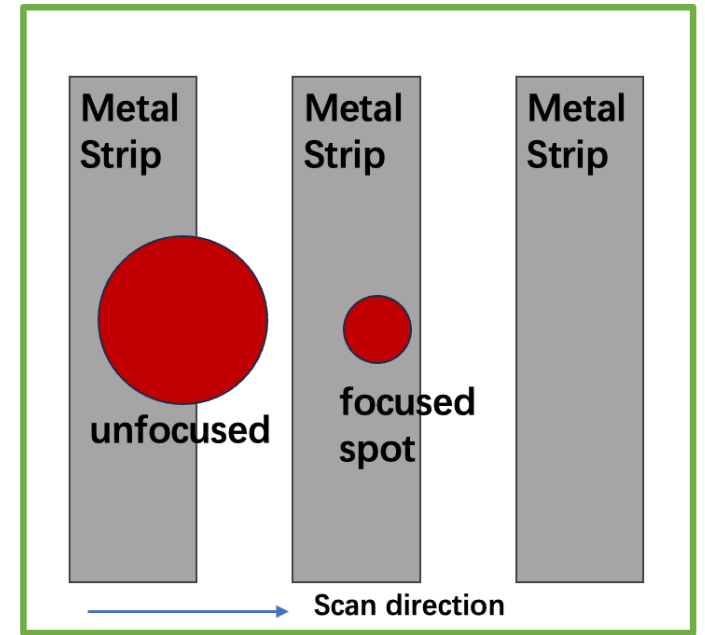
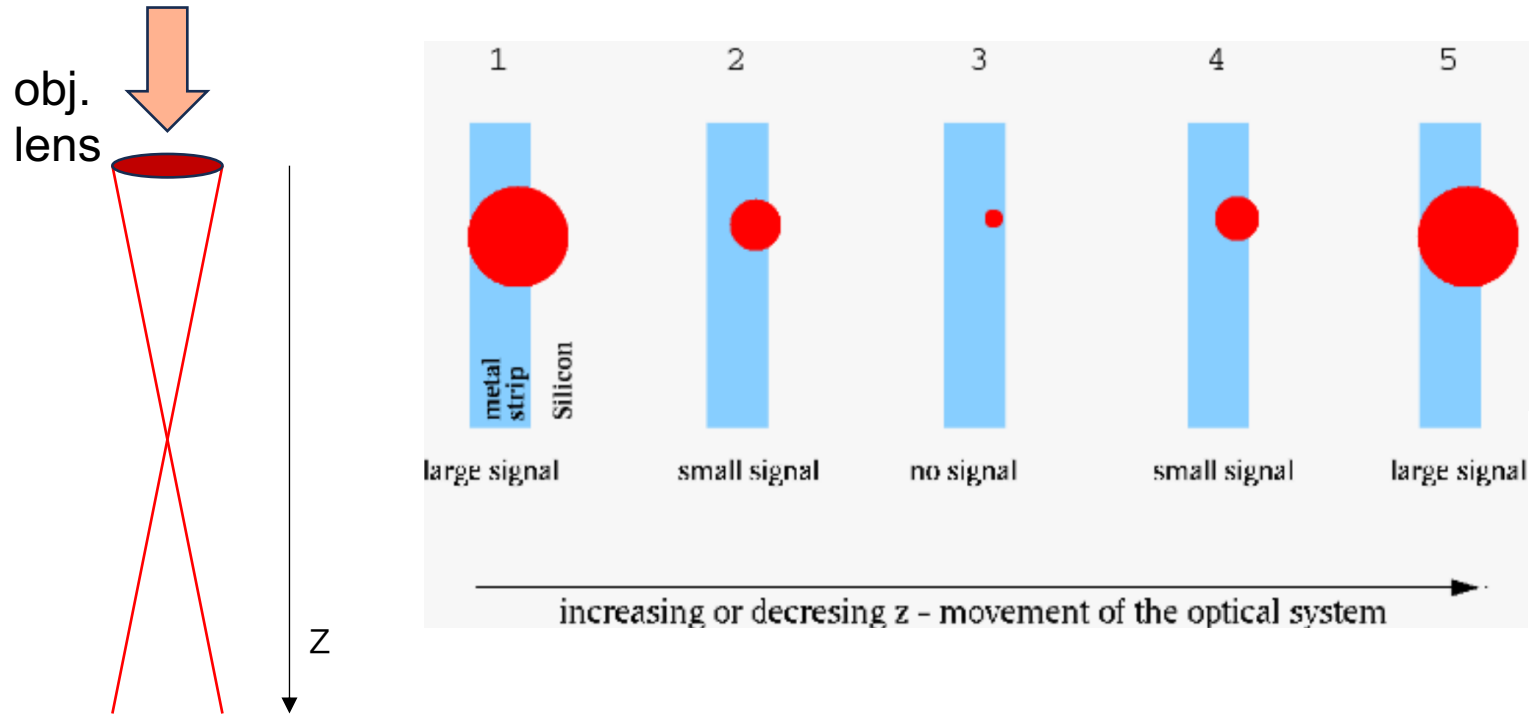


压电位移滑台



中国科学院高能物理研究所
Institute of High Energy Physics
Chinese Academy of Sciences

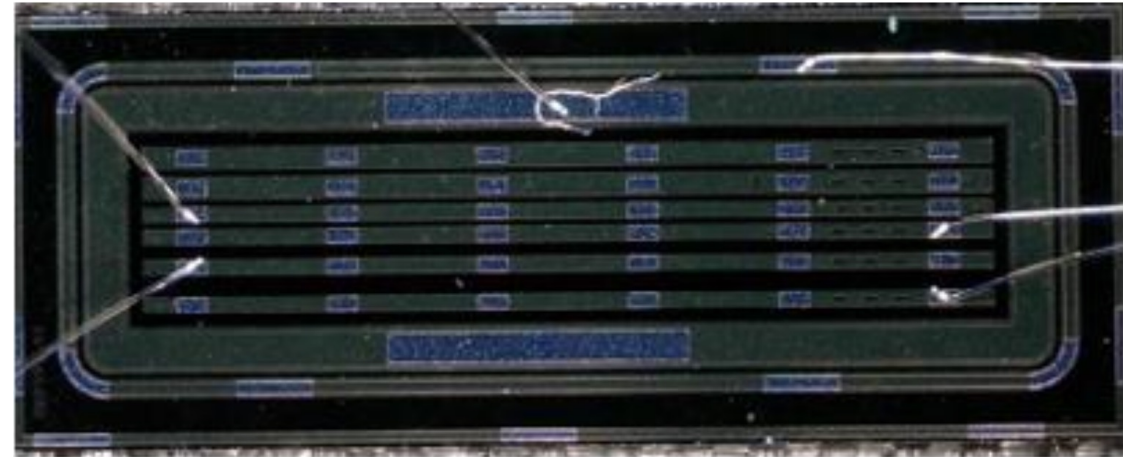
Focusing & Alignment



Two different methods for focusing adjustment

Focusing & Alignment

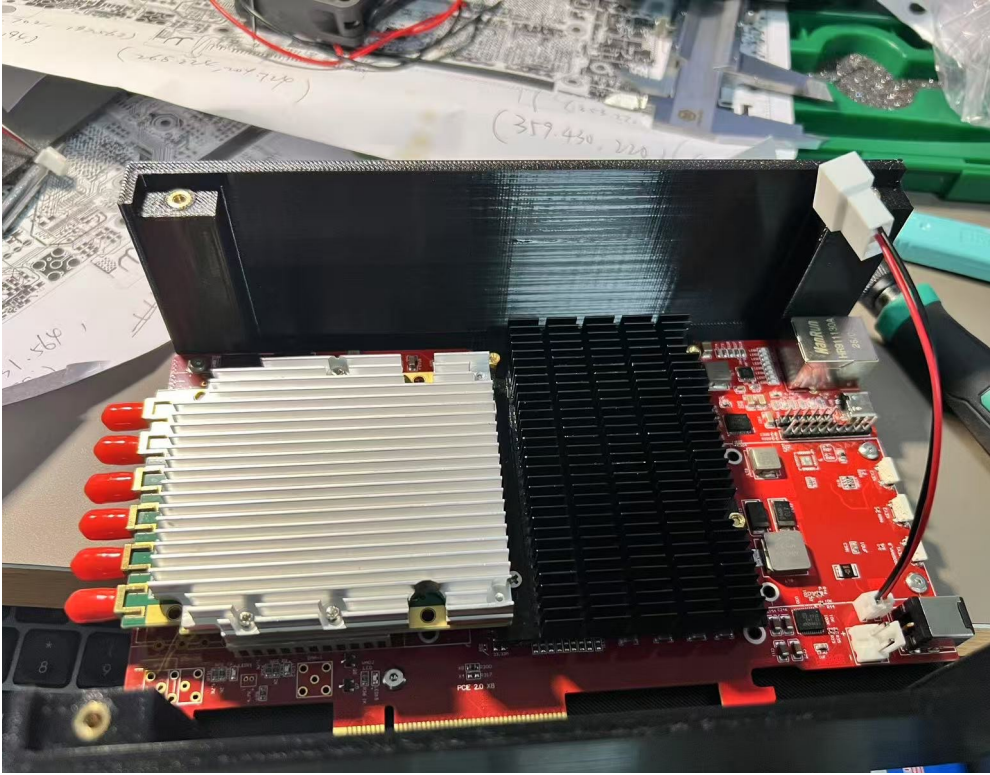
- The chip mounted on the board is prone to **rotation** in the x-y plane.
- Matching of the **original point** (or absolute position) is also required.
- Reconstruction & calibration methods are needed for such purposes



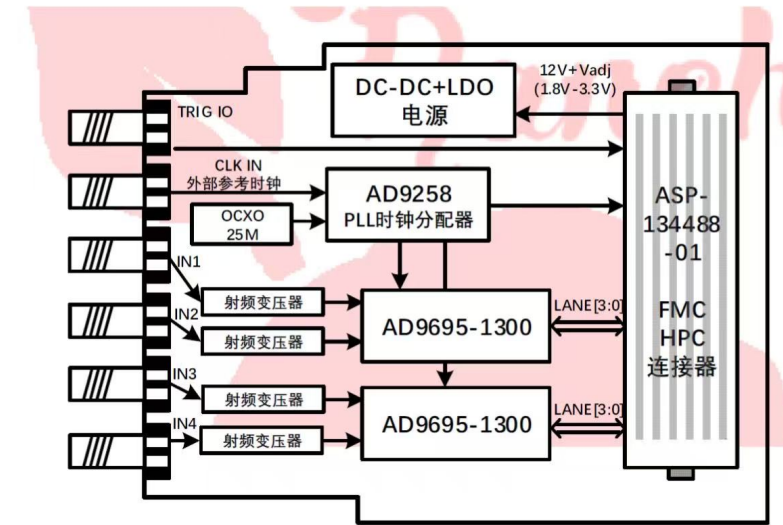
DAQ

- Baseline: Oscilloscope
 - 5~10Gsps sampling rate,
 - >1.5GHz bandwidth
- Option: FPGA + ADC
 - ADC12DJ3200 6.4Gsps FMC AD子卡 (1-ch 6.4 / 2-ch 3.2)
 - AD9695 1.25Gsps FMC AD子卡 (4-ch 1.25)
 - AD6688 / AD9208 3.0Gsps FMC AD子卡 (2-ch 3.0)
 - DC couple up to 900MHz bandwidth
 - AC couple 50M ~ 1GHz to 6GHz (Balun transformer)
 - Further study is also performed for **bandwidth & sampling rate** requirement
- Option: FPGA + customized TDC

4-ch ADC for waveform recording

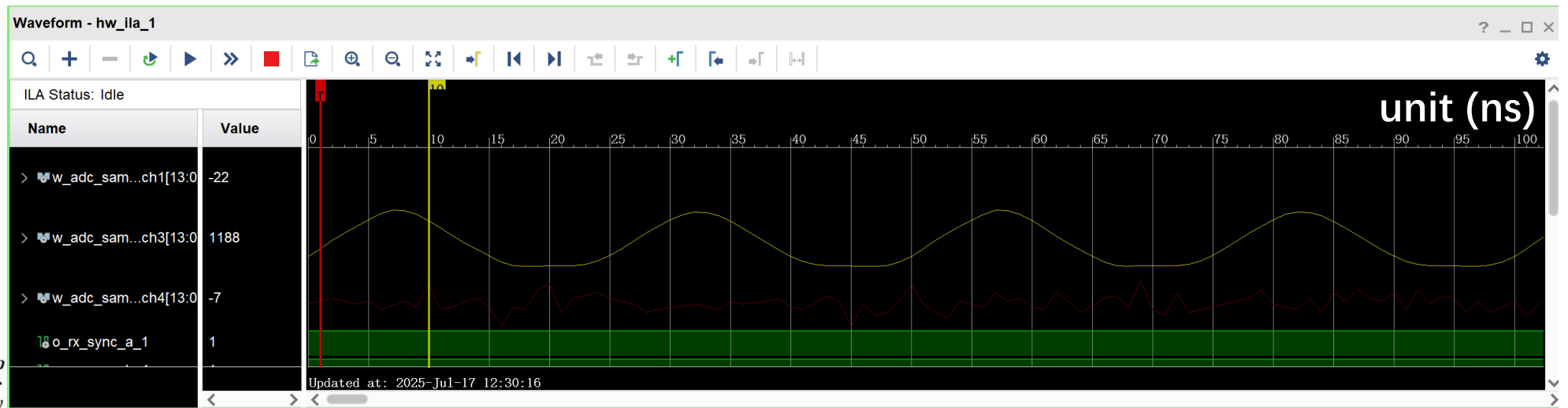
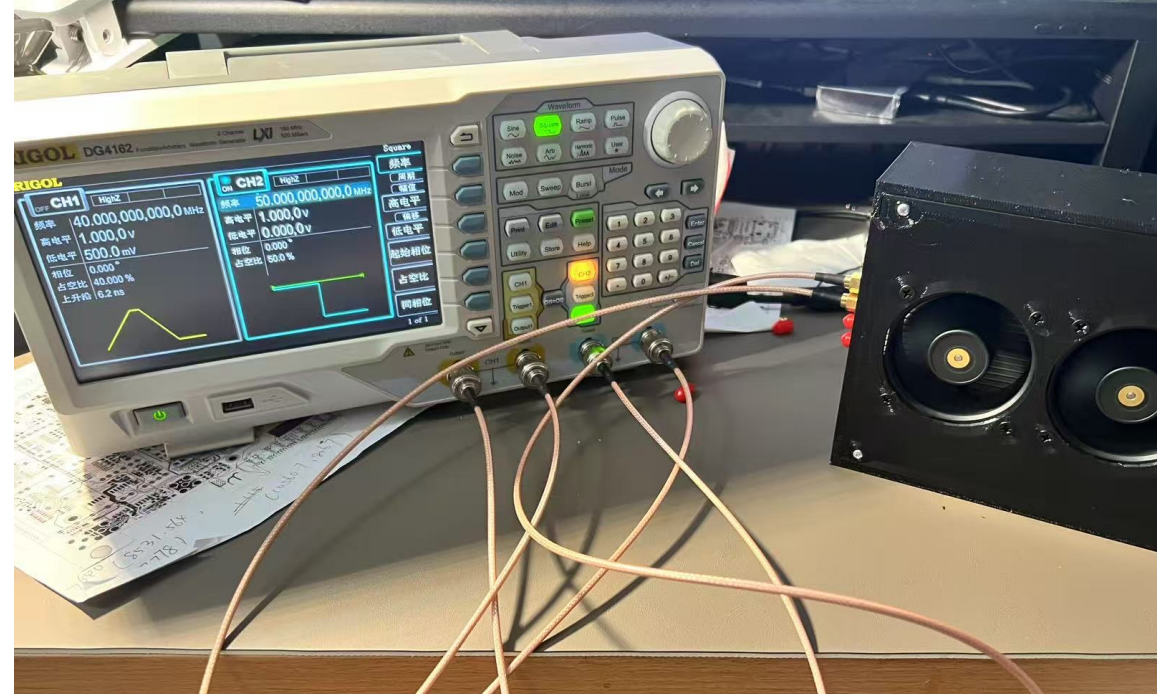


- 4ch ADC based on two AD9695 chips and AD9528 (1250 Msps), bandwidth 400k~500MHz (AC-coupled)



ADC test

- Signal injection with Rigol DG4162
- **Sine** 160MHz, **Pulse** 40MHz (6.2 ns rising edge), **Ramp**, **Square**, user-defined, etc.
- ILA triggered & monitored



Signal Shape Analysis for ADC requirement study

A typical pulse shape of LGAD signal

Rise time ~ 700 ps

Pulse width ~ 2.5 ns

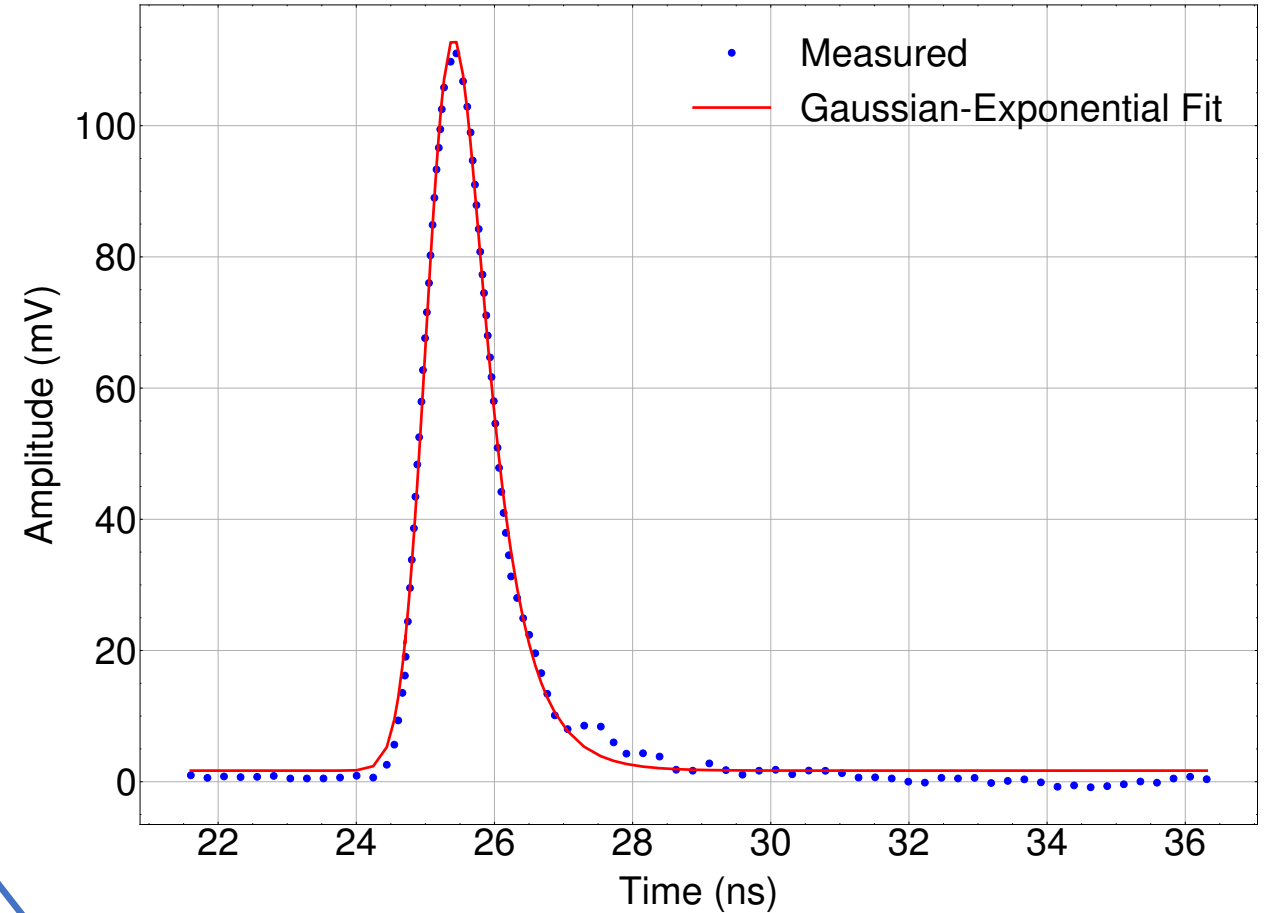
Fit function:

Gaussian-Exponential Convolution

Parameters:

- $A = 137.97$ mV
- $B = 1.69$ mV
- $t_0 = 25.13$ ns
- $\sigma = 0.320$ ns
- $\tau = 0.48$ ns (max to $1/e$)

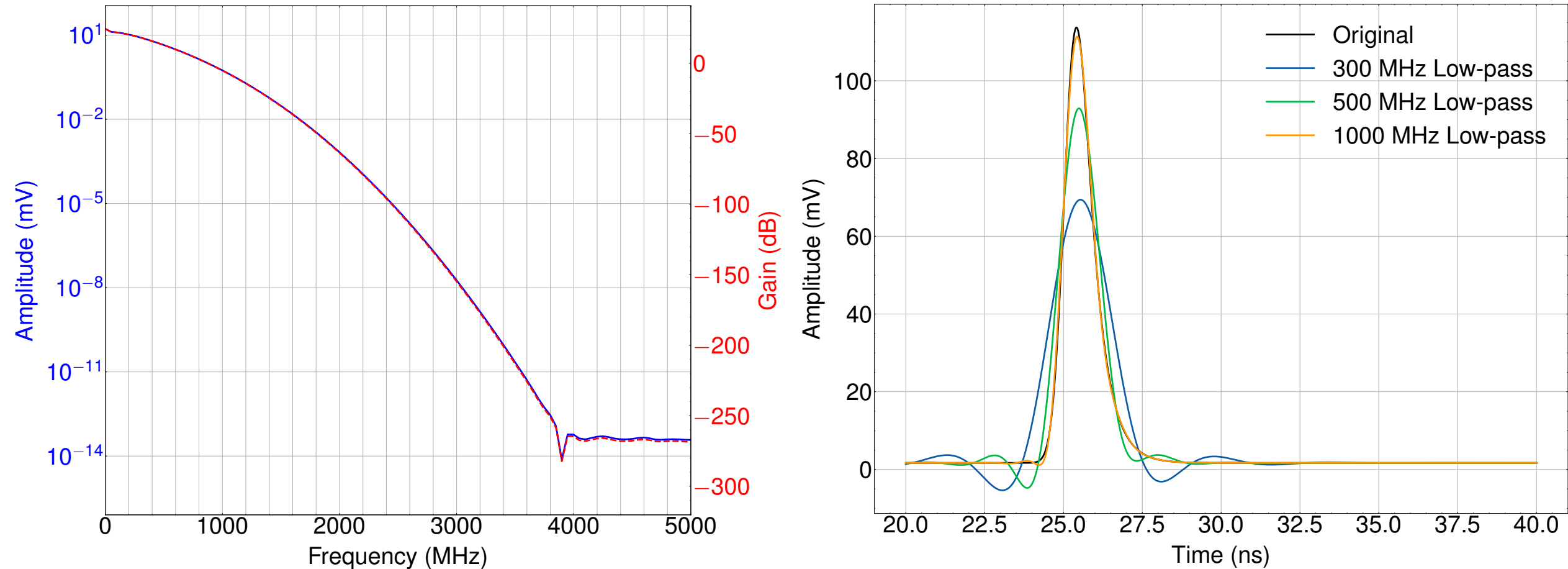
rise time (10% to 90%) $t_{\text{rise}} \approx 2.355 \sigma \approx 0.75$ ns



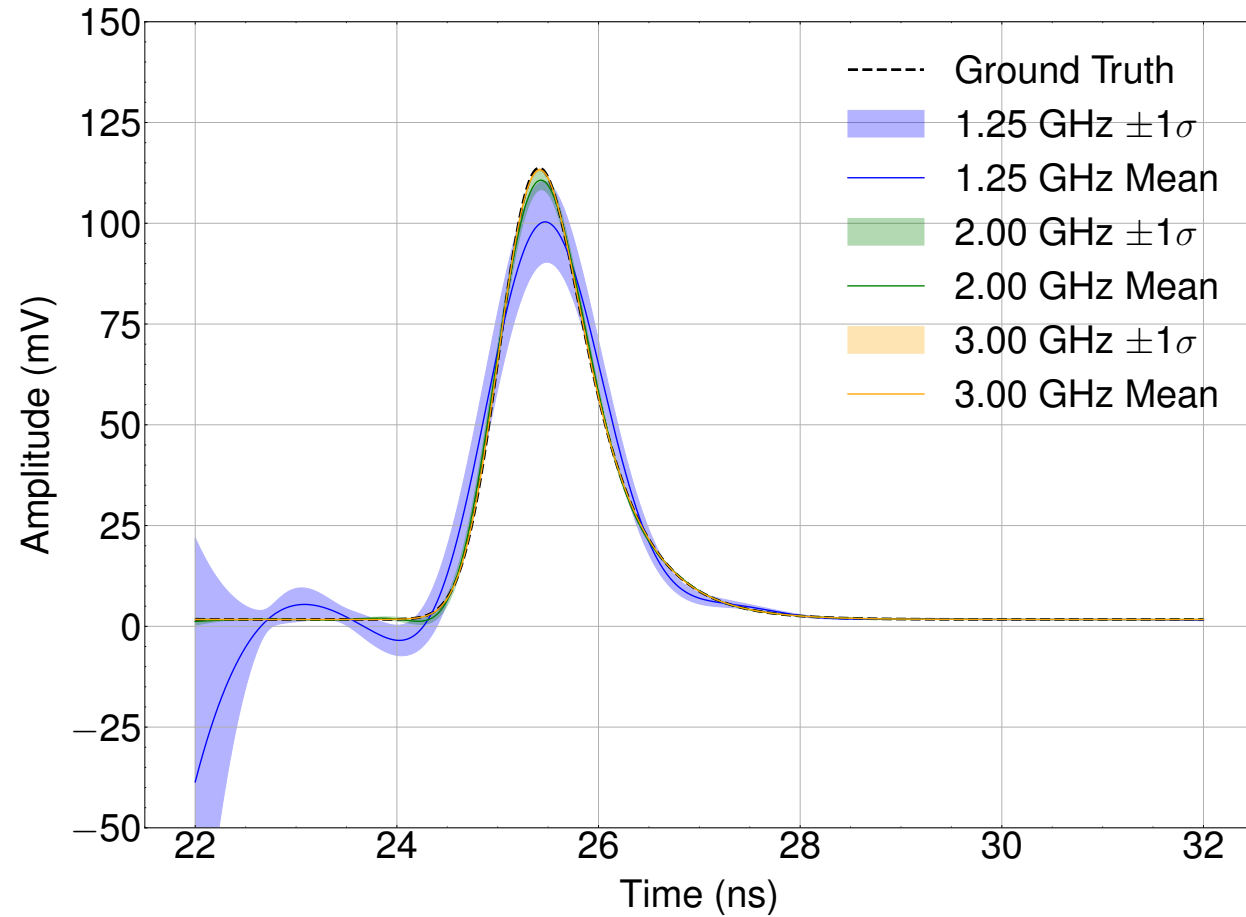
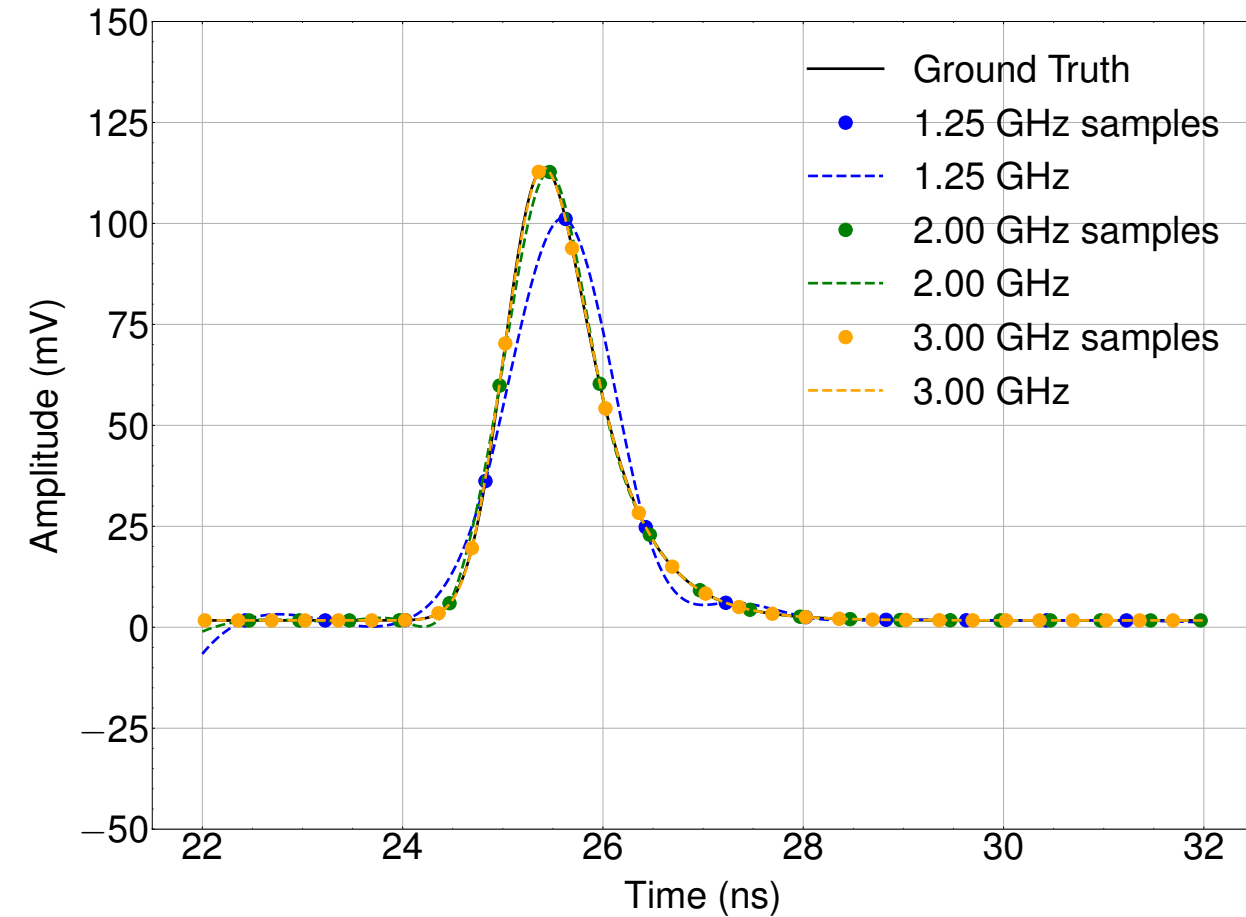
$$V(t) = A \cdot \exp\left(\frac{\sigma^2 - 2\tau(t - t_0)}{2\tau^2}\right) \cdot \left[1 + \operatorname{erf}\left(\frac{t - t_0 - \sigma^2/\tau}{\sqrt{2}\sigma}\right)\right] + B$$



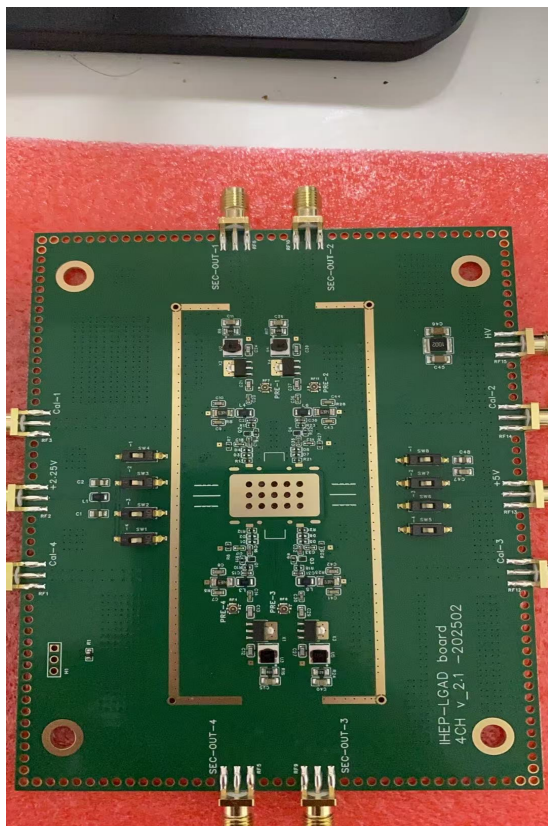
Distortion from insufficient bandwidth



Uncertainty from insufficient sampling rate

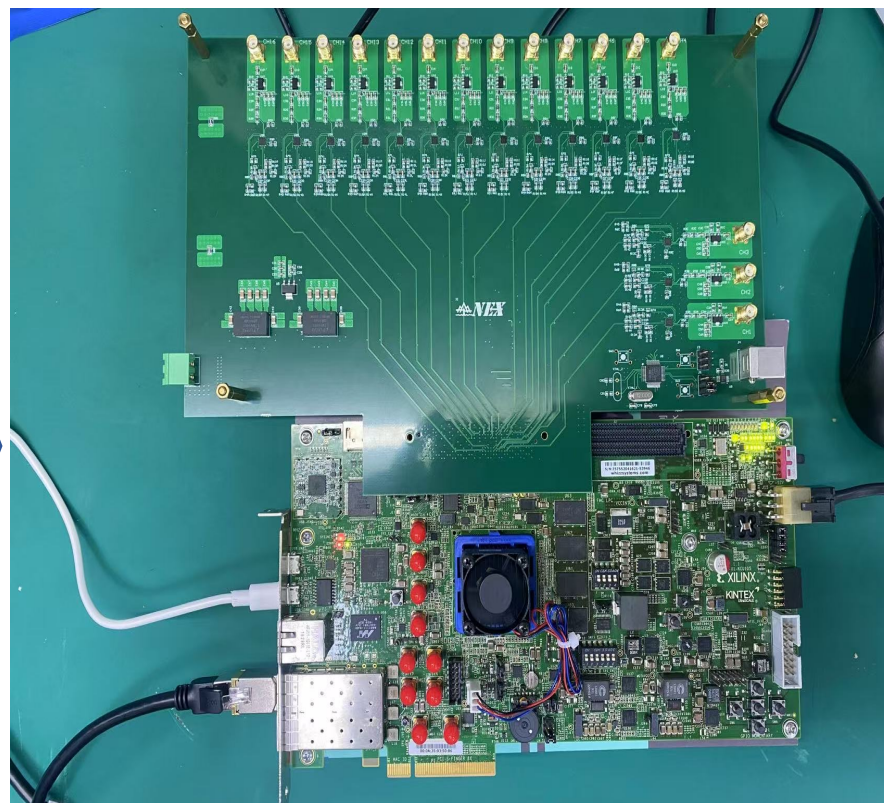


TDC scheme & test



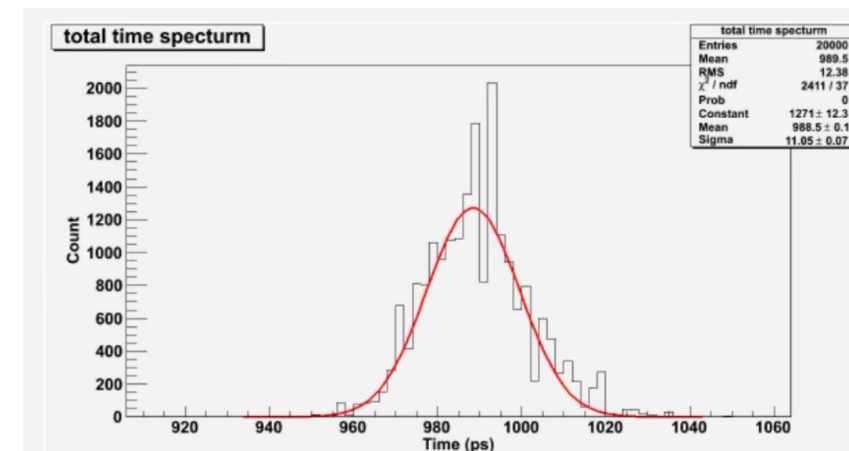
前端版

- 4通道 SMA输出



读出板

- 16通道 FMC接口
- Xilinx K7开发板搭载TDC模块



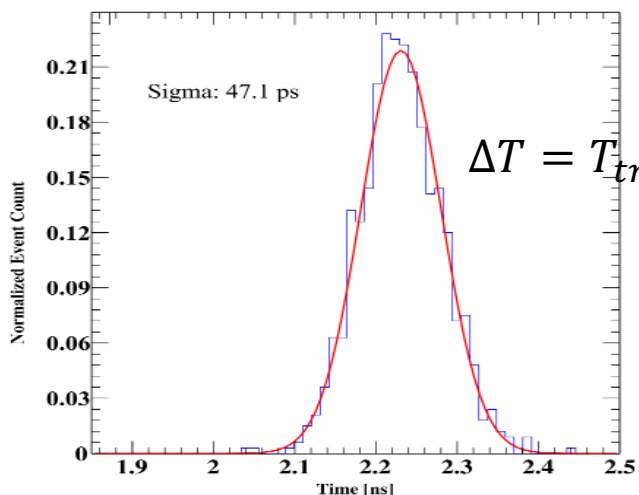
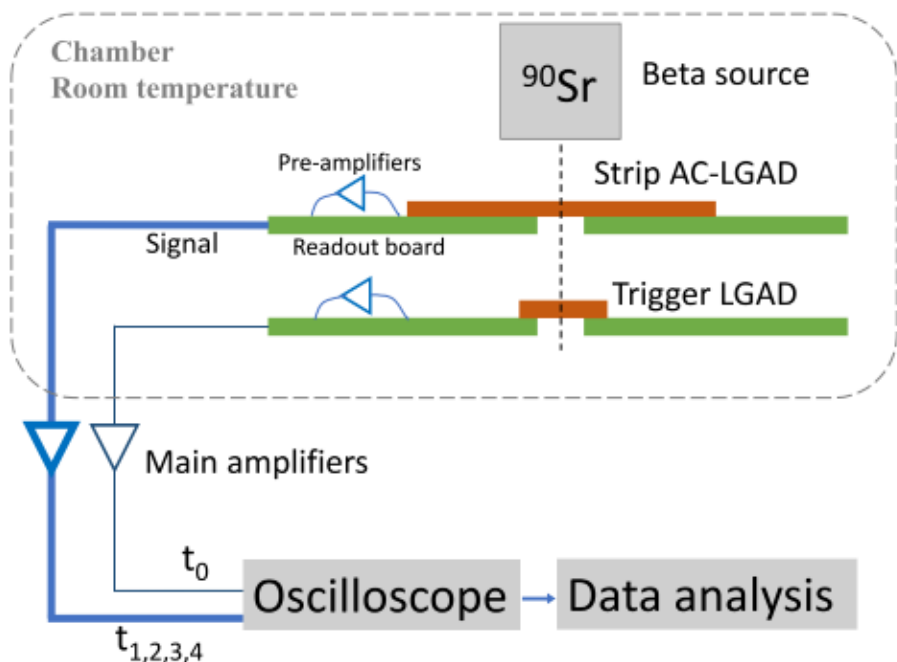
TDC初步测试结果, TOA精度~11 ps



Beta source & Beam test

Principals, methods & designs

^{90}Sr test & time resolution



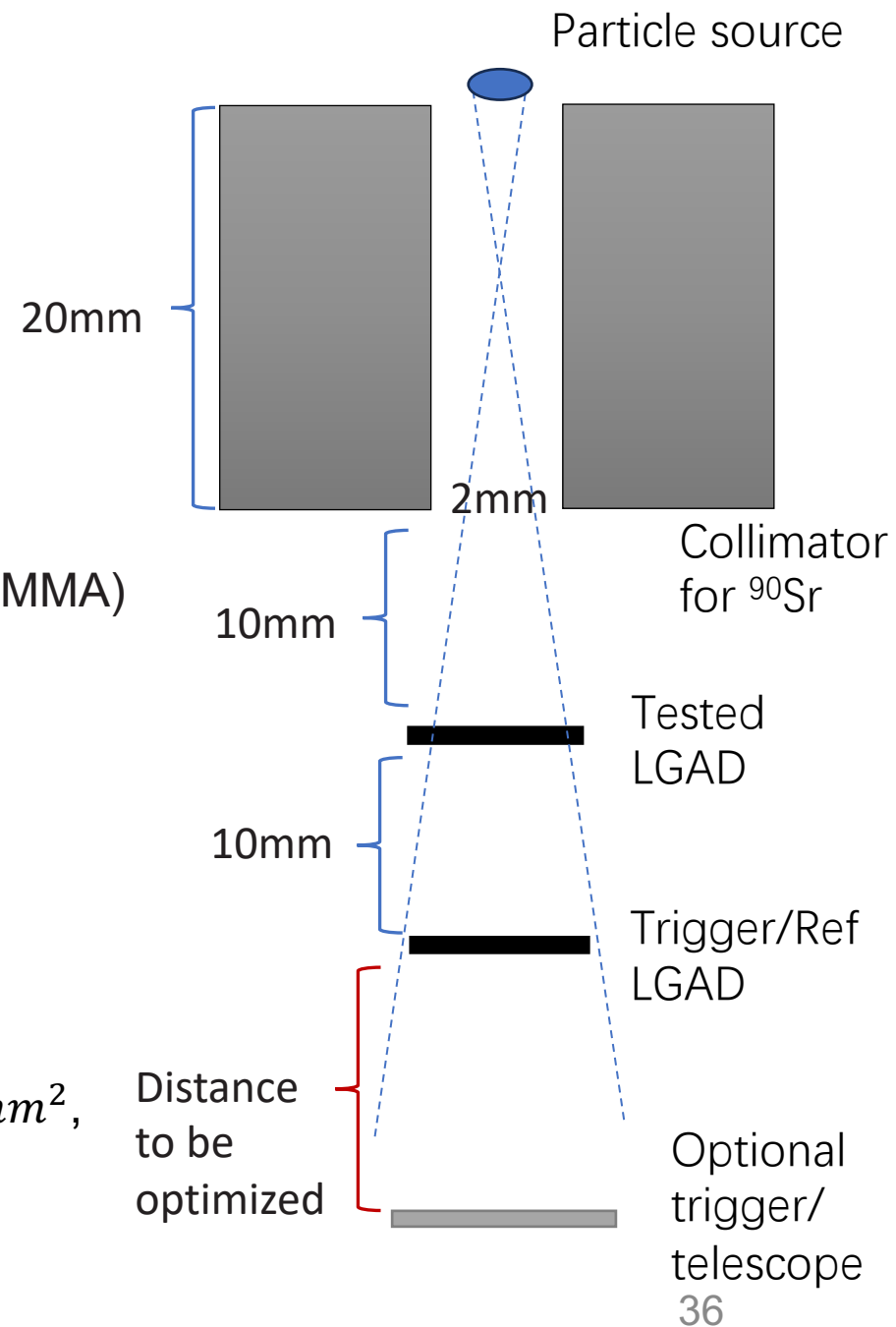
$$\Delta T = T_{trigger} - \frac{\sum a_i^2 T_i}{\sum a_i^2}$$

$$\sigma_t^2 = \sigma_{TimeWalk}^2 + \sigma_{Landau}^2 + \sigma_{Jitter}^2 + \sigma_{TDC}^2 + \sigma_{Distortion}^2$$

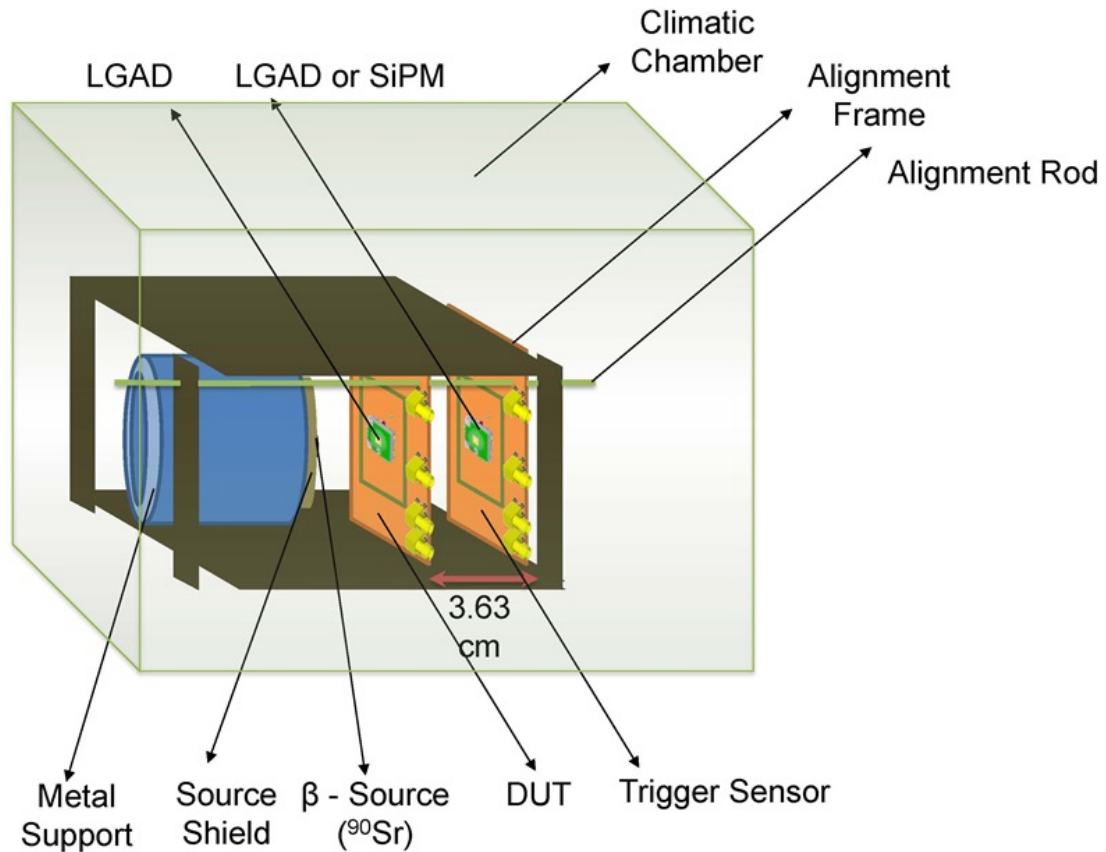
- Time walk effect $\sigma_{TimeWalk}$, 与信号幅值分布、放大器响应速度有关
- Landau effect σ_{Landau} 由能量沉积（空间、时间）不均匀性引起
- Jitter effect $\sigma_{Jitter} = \frac{N}{dV/dt} \propto t_{rise} / \frac{S}{N}$, 由噪声与上升沿速度共同决定
- $\sigma_{TDC} = \Delta t / \sqrt{12}$ (Δt : TDC bin 宽, 即时间分辨单元)
- Distortion 信号在读出链路（电缆、放大器、ADC）中形状被展宽、反射、非线性失真

^{90}Sr / beam test setup

- β 源 ^{90}Sr
 - a) 面源, 假设活性区域 $d=1\text{mm}$
 - b) 豁免源(V类)活度 1e4 Bq
- 准直 (PMMA + Al + Cu + PMMA) 减少 β 韧致辐射、同时吸收 γ 和软X
 - a) 内直径2mm, 长20mm (1mm PMMA, 3mm Al, 15mm Cu, 1mm PMMA)
 - b) 距离LGAD 10mm, 距离trigger LGAD 20mm
- e^- 角度带来的 $\Delta t \sim 0.1\text{ps}$
- 穿过准直器的粒子 $R_{out} \sim 10\text{个/s}$
- LGAD (7.4mm $\times$ 2.85mm)
- 穿过trigger LGAD的粒子 $R_{\text{trigger LGAD}} \sim 5\text{个/s}$
- Optional trigger: 塑料闪烁体/石英 (切伦科夫) + fast SiPM (1.3 $\times$ 1.3mm², 3 $\times$ 3mm²), can also be used as **telescope** for the beam test



^{90}Sr / beam test setup



Stack of LGAD planes and the trigger plane



Convenient laboratory tool to measure the gain and the timing resolution.

No position resolution.



Summary & Plan

- I-V & C-V test  (almost), schematic & software are ready, waiting for HV source & LCR meter
- Currently preparing for the laser test & lab building 
 - Optical setup
 - Power sources & meters & other infrastructures
- Design of **Sr-90** & **beam test** setup for time resolution study is also on-going , preparing for beam reservation 
- Participate in the **AC-LGAD fabrication** run and process flow at **SIMIT**. 
- More results & news will be updated later

